

# Hi3798CV20PB VER.A

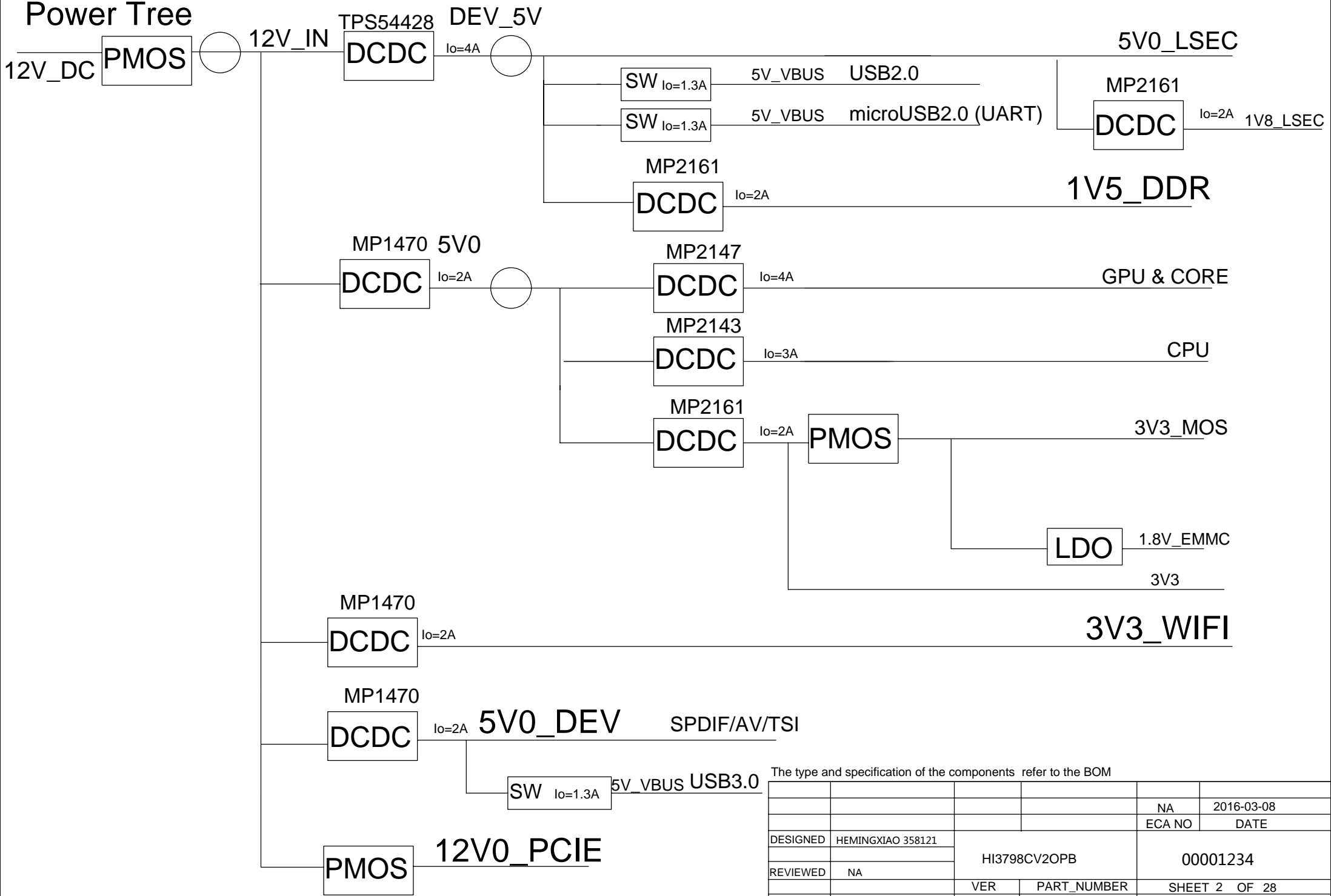
Hi3798CV200 Open Source Board  
4 layers PCB with DDR3 8bit x 4  
Board Size:160mm x 120mm x 1.6mm  
Hi3798CV20PB VER.A\_V1.0.0.0

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The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV20PB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 1 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

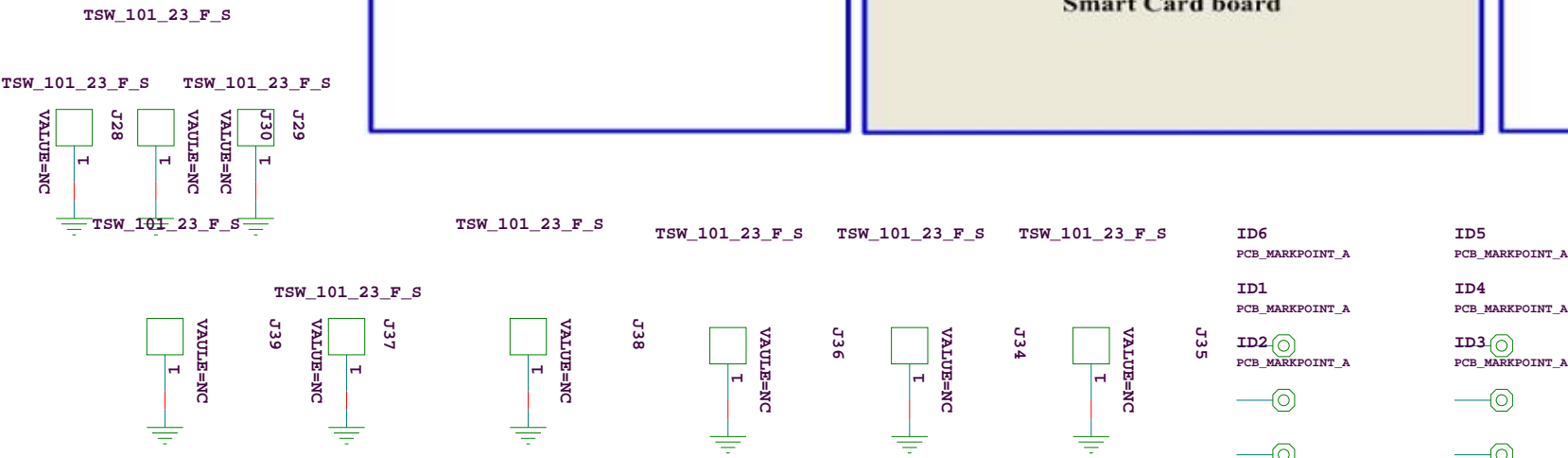
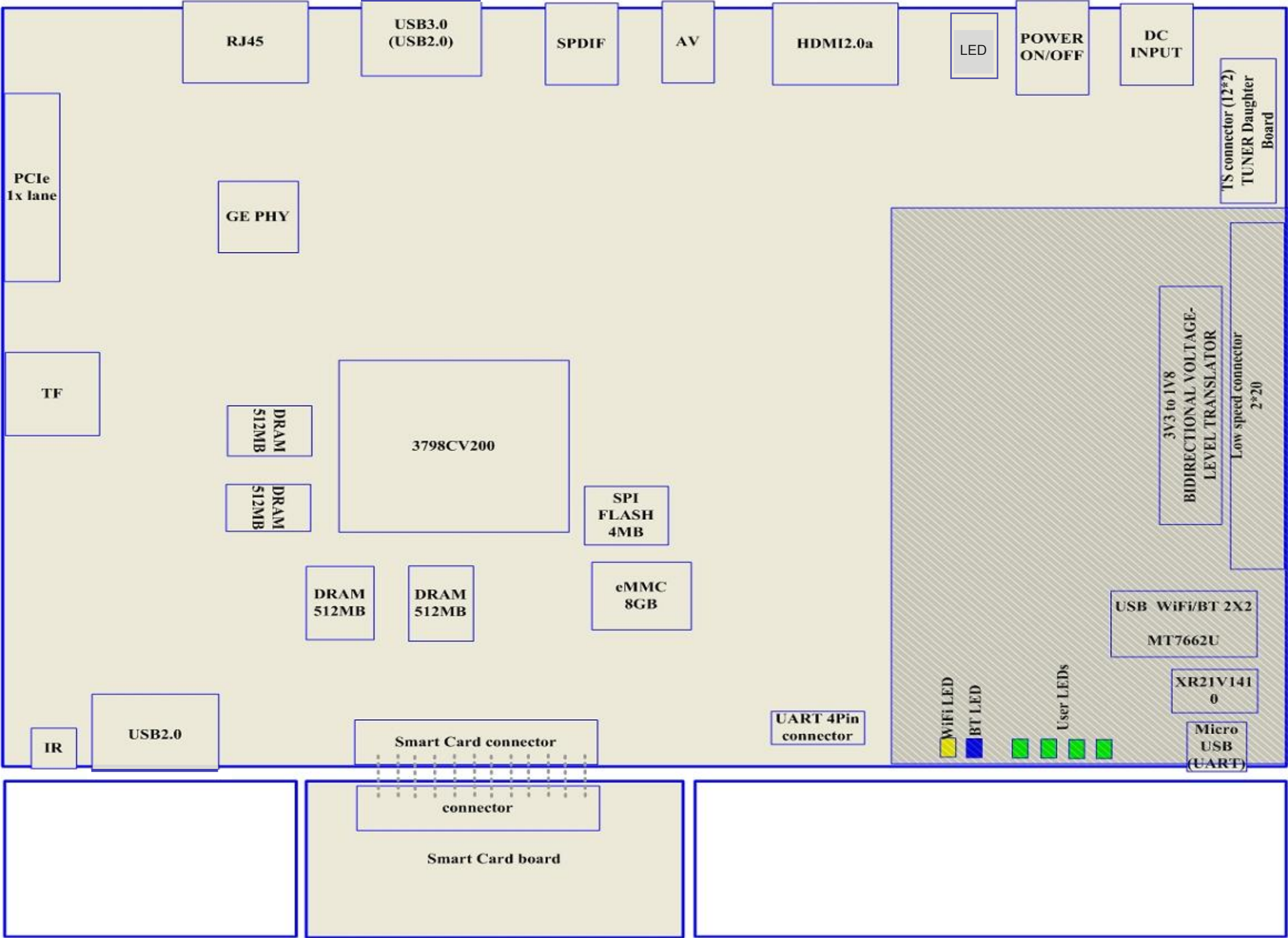
Power Tree



The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 2 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

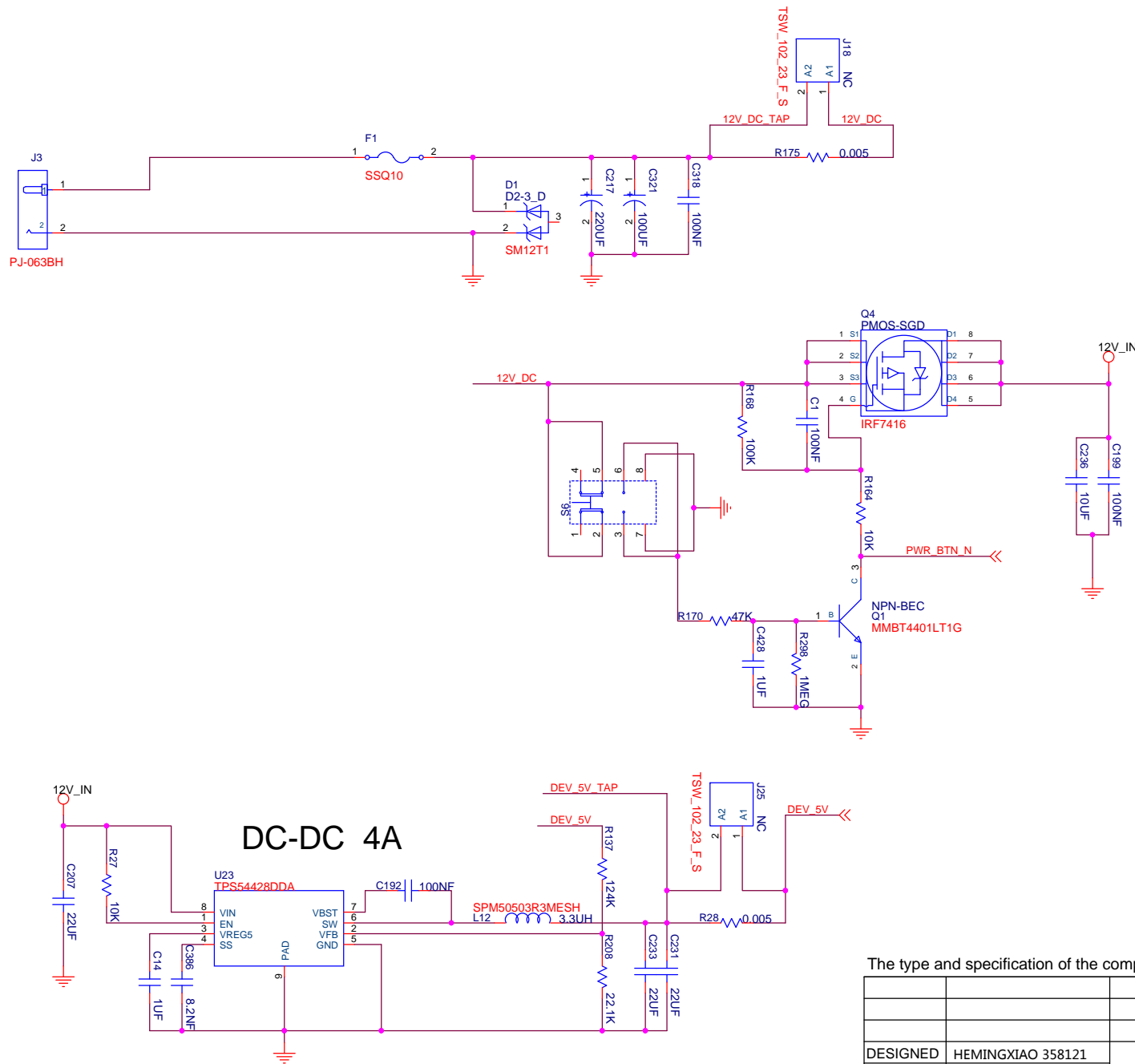
Block Diagram



The type and specification of the components refer to the BOM

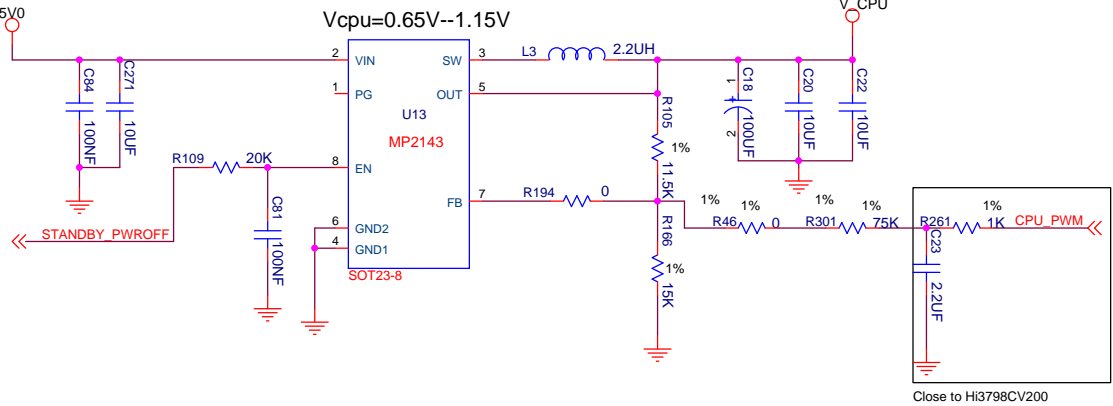
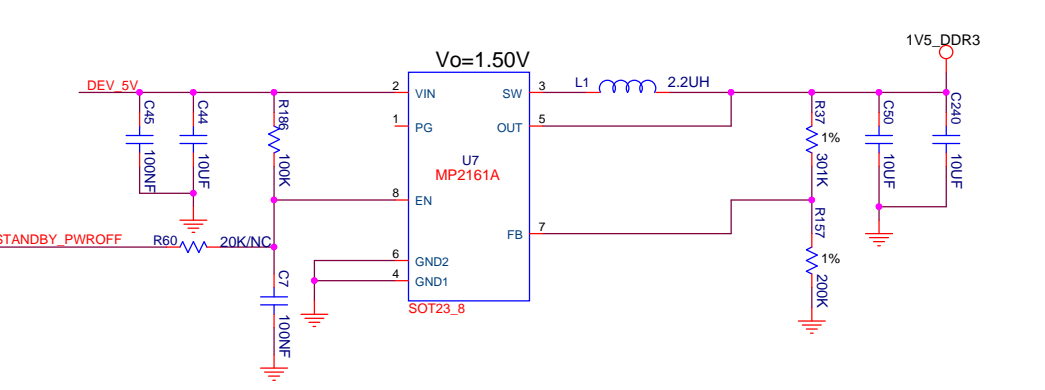
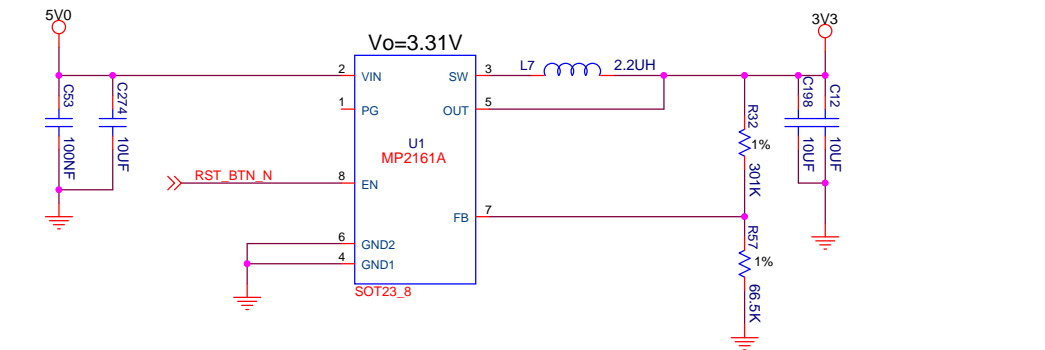
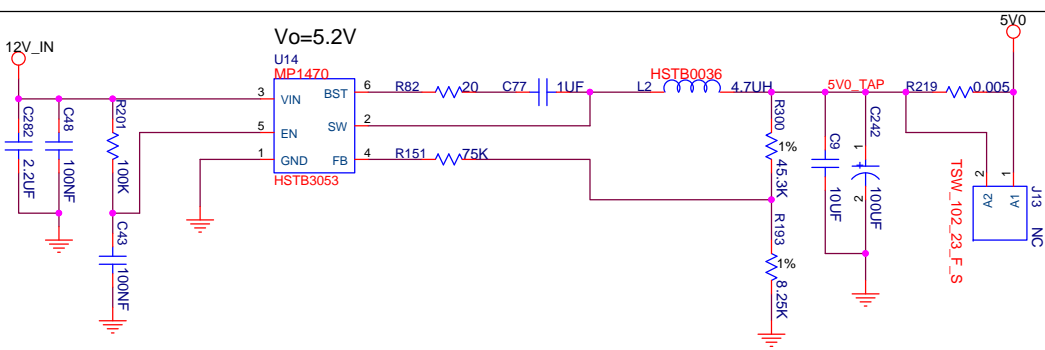
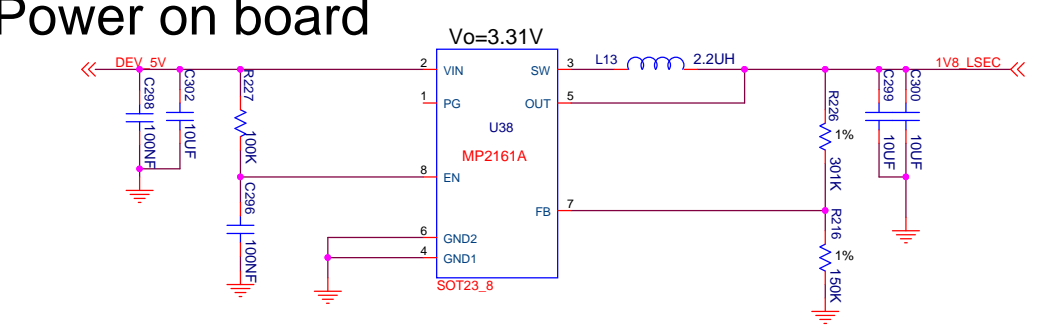
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|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | NA                | HI3798CV20PB |             | 00001234             |            |
| REVIEWED |                   | VER          | PART_NUMBER | SHEET 3 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

Power on board

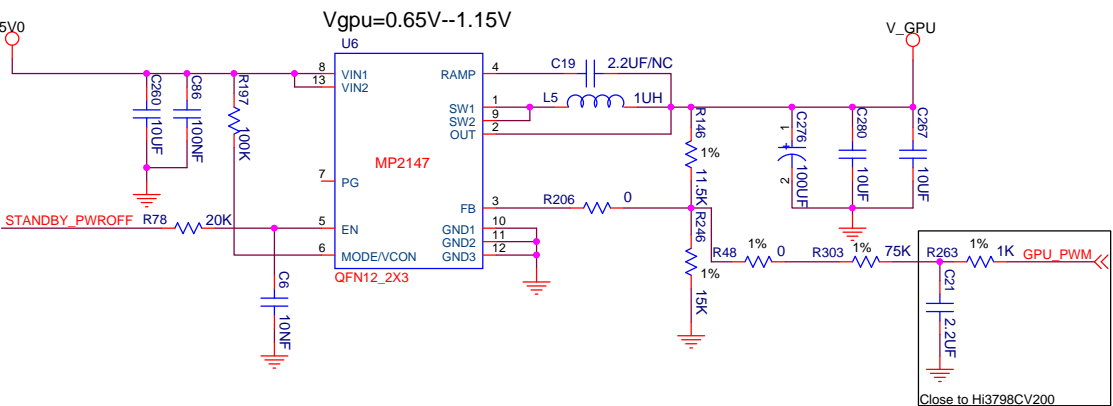


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|   |                   |              |             | ECA NO               | DATE       |
| DESIGNED  | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED  | NA                |              |             |                      |            |
|   |                   | VER          | PART_NUMBER | SHEET 4 OF 28        |            |
|   |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

Power on board



The 3A DC-DC with fast transient response(such as COT or ACOT control) must be selected for the CPU power.

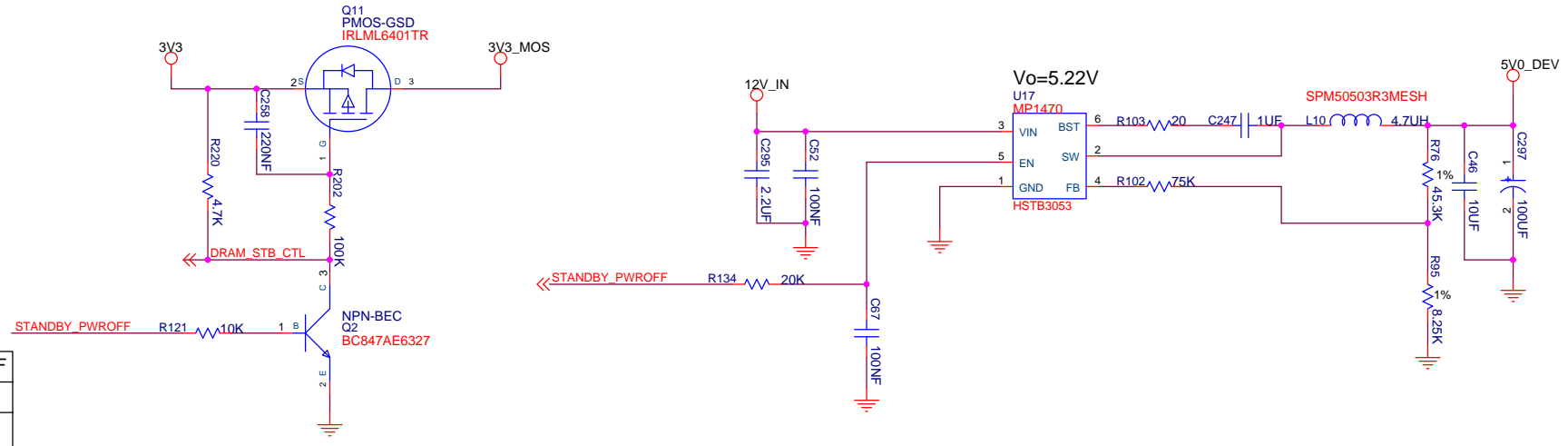


The 4A DC-DC with fast transient response(such as COT or ACOT control) must be selected for the GPU power.

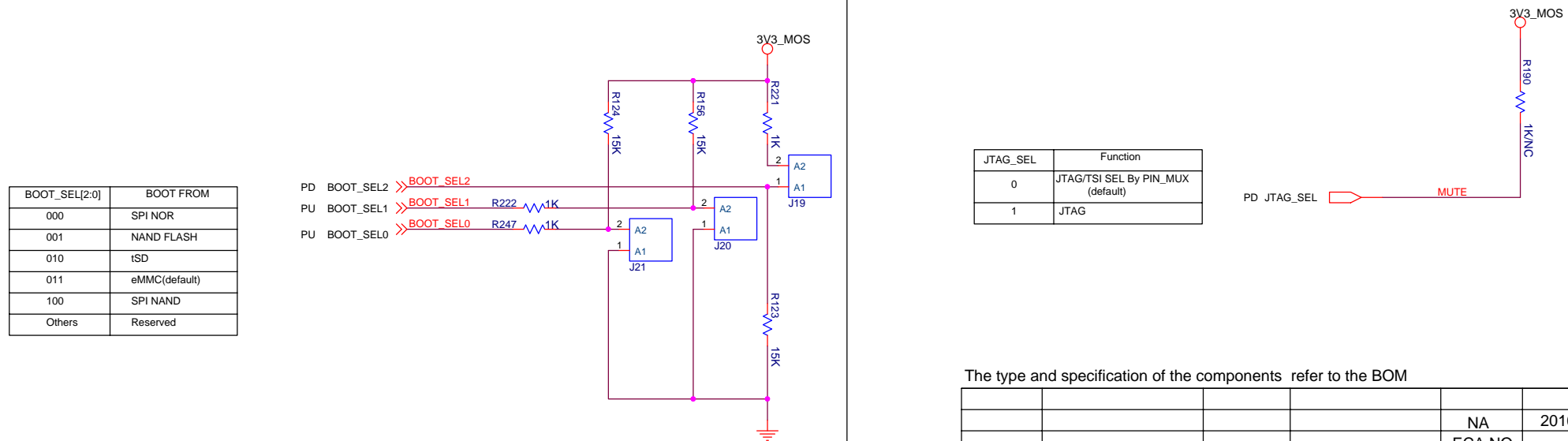
The type and specification of the components refer to the BOM

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|----------|-------------------|--------------|-------------|----------------------|------------|
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|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                | VER          | PART_NUMBER | SHEET 5 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

## Power Ctrl



| STANDBY_PWROFF |           |
|----------------|-----------|
| 0              | Power Off |
| 1              | Power On  |



| JTAG_SEL | Function                             |
|----------|--------------------------------------|
| 0        | JTAG/TSI SEL By PIN_MUX<br>(default) |
| 1        | JTAG                                 |

PD JTAG\_SEL  MUTI

The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
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| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
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|          |                   | VER          | PART_NUMBER | SHEET 6 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |
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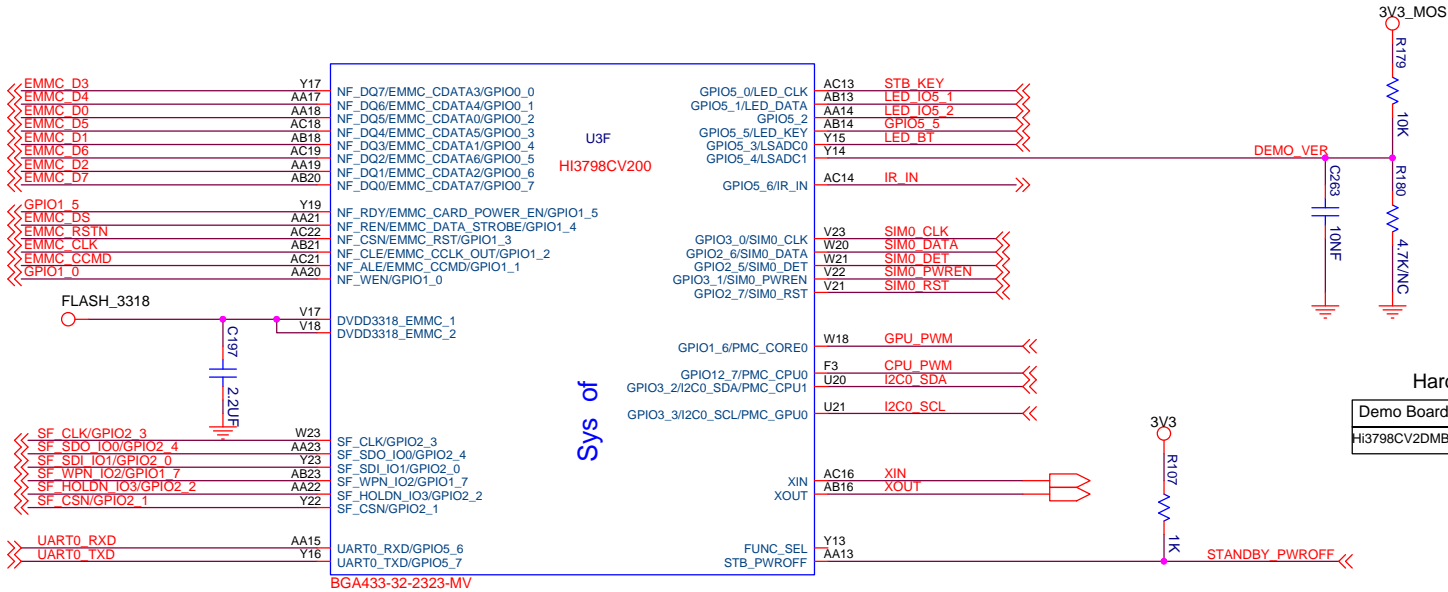
Unit 1 of Hi3798CV200(FLASH/UART/IR/PWM/XTAL)

\*\*\*\*\*Low Speed ADC Information\*\*\*\*\*

Input Voltage Range: 0V - 3.3V( > 3.63V is forbidden)

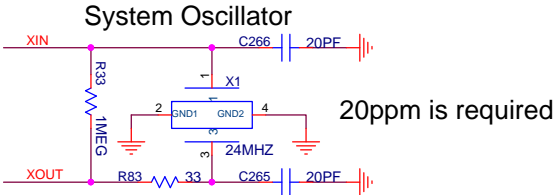
LSADC0: used as Key input or Power detected

LSADC1: used as Hardware Version detected



Hardware Version

| Demo Board   | DDR Config   | Voltage  |
|--------------|--------------|----------|
| Hi3798CV2DMB | DDR3 8 Bit*4 | 3.3V +3% |



The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 7 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

# Unit 2 of Hi3798CV200(HDMI TX/VDAC/ADAC)

## \*\* HDMI Design guideline \*\*

### A.routing

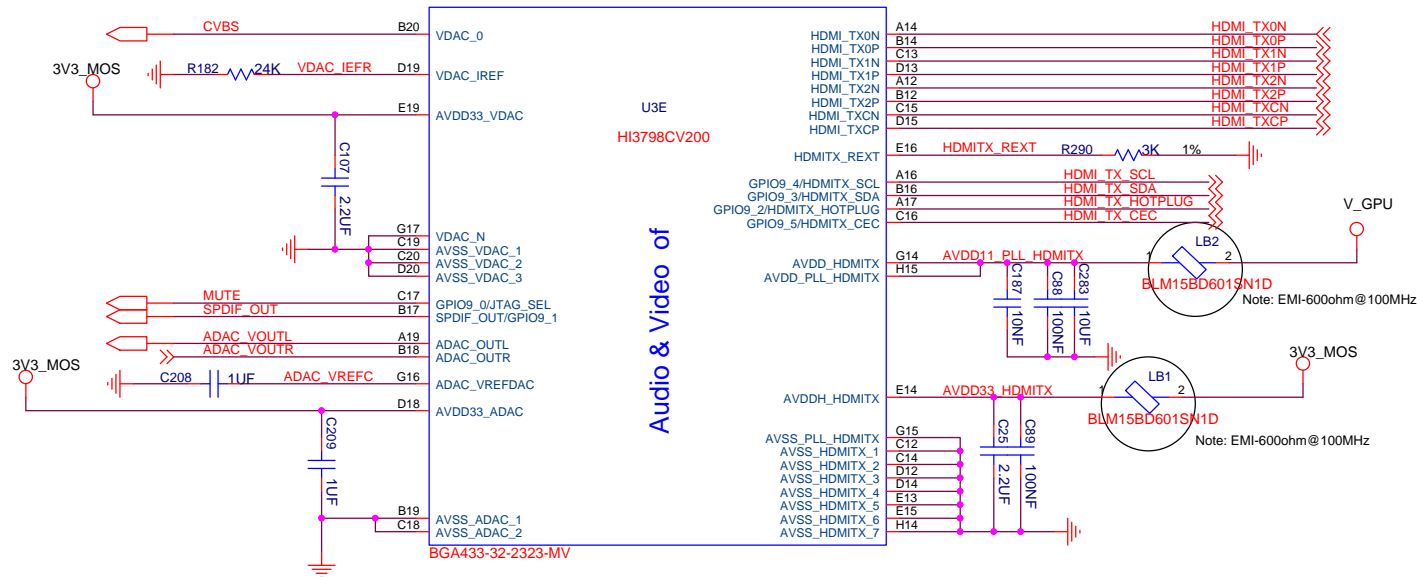
- 1.Route as 100 Ohm differential impedance.
- 2.Differential pairs should be routed on TOP layer only.

### B.trace length

- 1.The length for the differential pairs should be less than 5 inches.
- 2.Match trace length of differential pairs, 5 mils max within a pair.

### C.component selection

- 1.REXT resistor should be 3K Ohm +/-1%.
- 2.ESD components are suggested for ports protection.
- 3.All equivalent capacitance of ESD components should be < 0.35pF.



## \*\* Audio & Video Design guideline \*\*

### A.VIDEO

- 1.VIDEO REXT resistor should be 12K +/-1% precision for full current model, and 24K +/-1% precision for quarter current model
- 2.REXT/COMP should be traced as short as possible, and isolated from all other traces.

### B.AUDIO

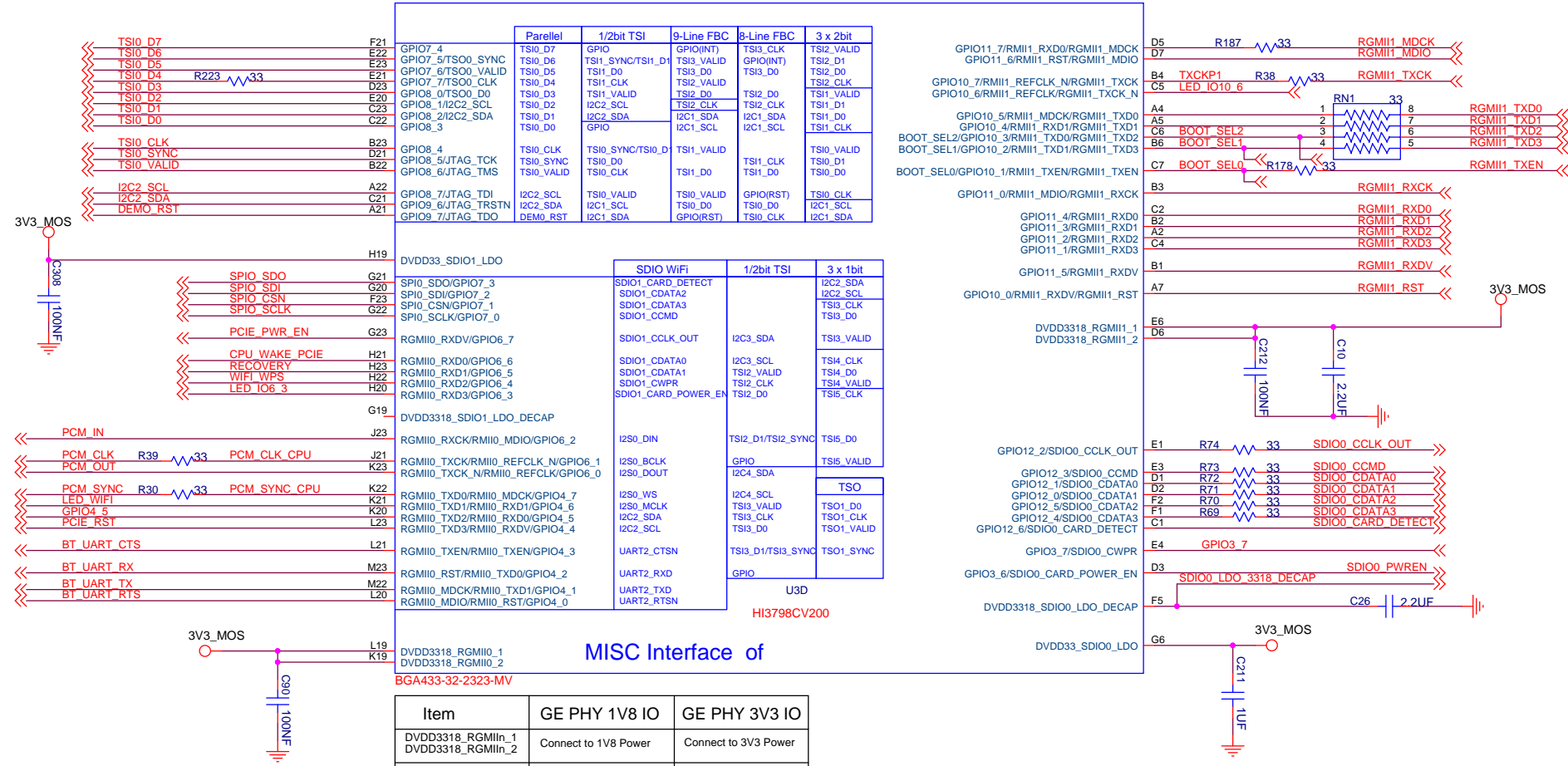
- 1.VREF should be traced as short as possible, and isolated from all other traces.

The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV20PB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 8 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |



Unit 3 of Hi3798CV200(RGMII/RMII/SDIO/TS)



| Item                                     | GE PHY 1V8 IO  | GE PHY 3V3 IO  |
|--|--|--|
| DVDD3318_RGMIIIn_1<br>DVDD3318_RGMIIIn_2 | Connect to 1V8 Power   | Connect to 3V3 Power   |
| Pin Mux Setting<br>in HiRegBin Tool      | RGMIIIn_TXEN_1V8<br>RGMIIIn_TXD3_1V8<br>RGMIIIn_TXD2_1V8<br>RGMIIIn_TXD1_1V8<br>RGMIIIn_TXD0_1V8<br>RGMIIIn_TXCK_1V8 | RGMIIIn_TXEN<br>RGMIIIn_TXD3<br>RGMIIIn_TXD2<br>RGMIIIn_TXD1<br>RGMIIIn_TXD0<br>RGMIIIn_TXCK |

Note: n=0,1 for RGMII0 & RGMII1

\*\*\*\*\* Design Notes \*\*\*\*\*

1. DVDD33\_SDI01\_LDO is the Input of the inside LDO which is power supply for IO of SDIO1, and DVDD3318\_SDI01\_LDO\_DECAP is the decap pin of the LDO, connect 2.2uF to GND if 1V8 IOs are needed, others NC is OK.

2. DVDD3318\_RGMII0 is the power supply pin of J23/J21/K23/K22/K21/K20/L23/L21/M23/M22/L20, connect to 1V8 power if 1V8 IOs are needed, or connect to 3V3 power.

eg1. if SDIO1 is used as SDIO3.0, DVDD33\_SDI01\_LDO should be connected to 3V3 power, DVDD3318\_SDI01\_LDO\_DECAP should be connect 2.2uF to GND.

eg2. if RGMII0 in 1V8 IOs is used, DVDD33\_SDI01\_LDO should be connected to 3V3 power, DVDD3318\_SDI01\_LDO\_DECAP should be connect 2.2uF to GND, DVDD3318\_RGMII0 should be connect to 1V8.

eg3. All IOs are used as 3V3 IOs, DVDD33\_SDI01\_LDO and DVDD3318\_RGMII0 should be both connected to 3V3 power, DVDD3318\_SDI01\_LDO\_DECAP needn't be care, NC is OK.

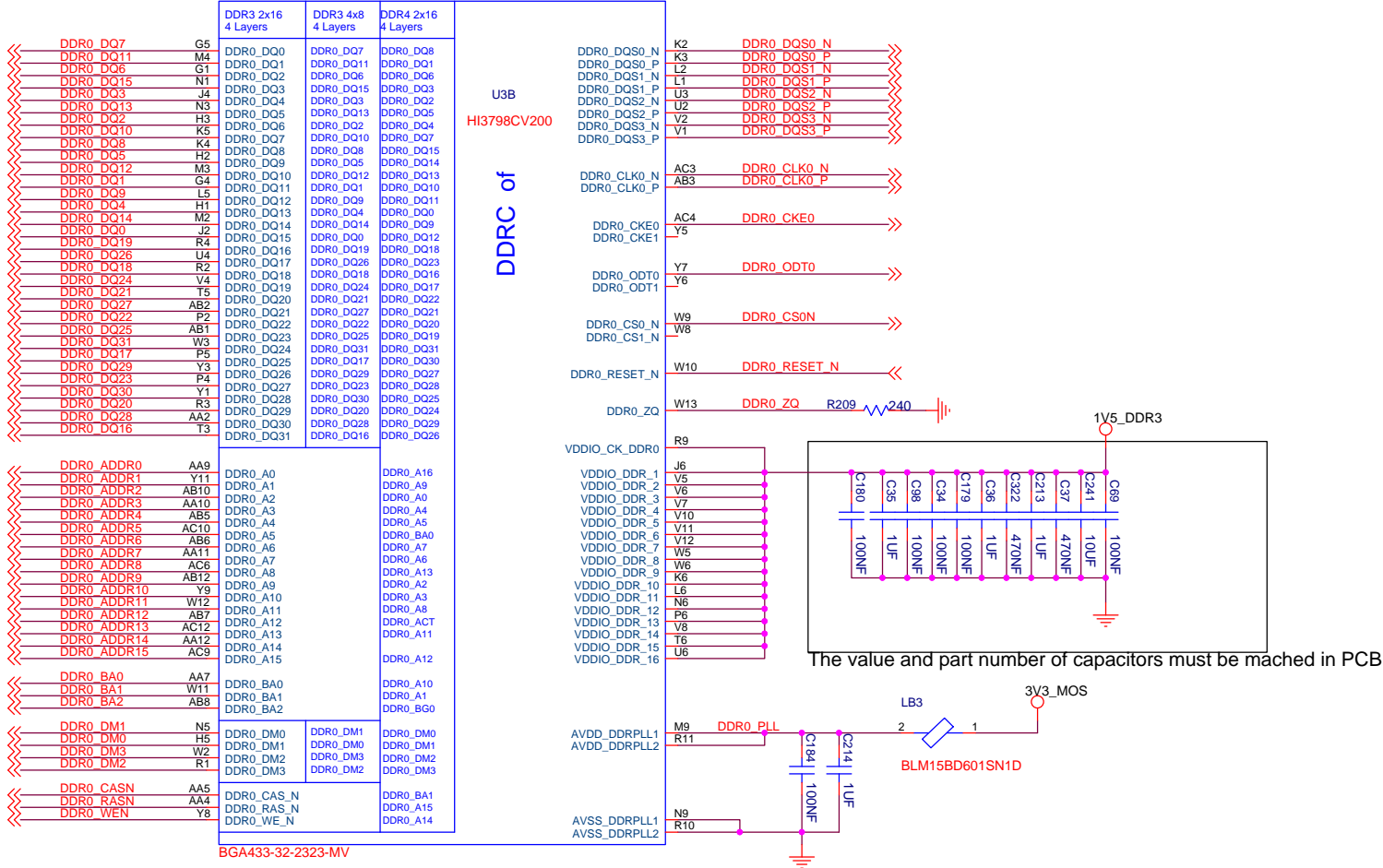
The type and specification of the components refer to the BOM

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|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV20PB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 9 OF 28        |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

|  |  |
|--|--|
| <p><b>** SATA&amp;PCIE Design guideline **</b></p> <p><b>A.routing</b></p> <ol style="list-style-type: none"> <li>1.Route as 100 Ohm differential impedance.</li> <li>2.Differential pairs should be routed on TOP layer only.</li> </ol>                        |  |
| <p><b>B.trace length</b></p> <ol style="list-style-type: none"> <li>1.The length for the differential pairs should be less than 5 inches.</li> <li>2.Match trace length of DP and DM differential pairs, 10 mils max within a pair.</li> </ol>                   |  |
| <p><b>C.component selection</b></p> <ol style="list-style-type: none"> <li>1.SATA:The value of capacitors for AC coupling should be &lt;=12nF,default 10nF</li> <li>2.PCIE:The value of capacitors for AC coupling should be &lt;=200nF,default 100nF</li> </ol> |  |

| The type and specification of the components refer to the BOM |                   |              |             |                      |            |
|---|-------------------|--------------|-------------|----------------------|------------|
|   |                   |              |             | NA                   | 2016-03-08 |
|   |                   |              |             | ECA NO               | DATE       |
| DESIGNED  | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|   |                   |              |             |                      |            |
| REVIEWED  | NA                |              |             |                      |            |
|   |                   | VER          | PART_NUMBER | SHEET 10 OF 28       |            |
|   |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

Unit 5 of Hi3798CV200(DDRC)



\*\* DDR Design guideline \*\*

A.general suggestion

- 1.Hi3798CV200 supports DDR3/DDR3L/DDR4
- 2.Hi3798CV200 supports up to 2GB DDR3.
- 3.The circuit of DDR\_VREF\_CA and DDR\_VREF\_DQ must be independent.
- 4.Please copy the decoupling capacitor design from hisilicon demo board.
- 5.3V3 DDRPLL is needed.

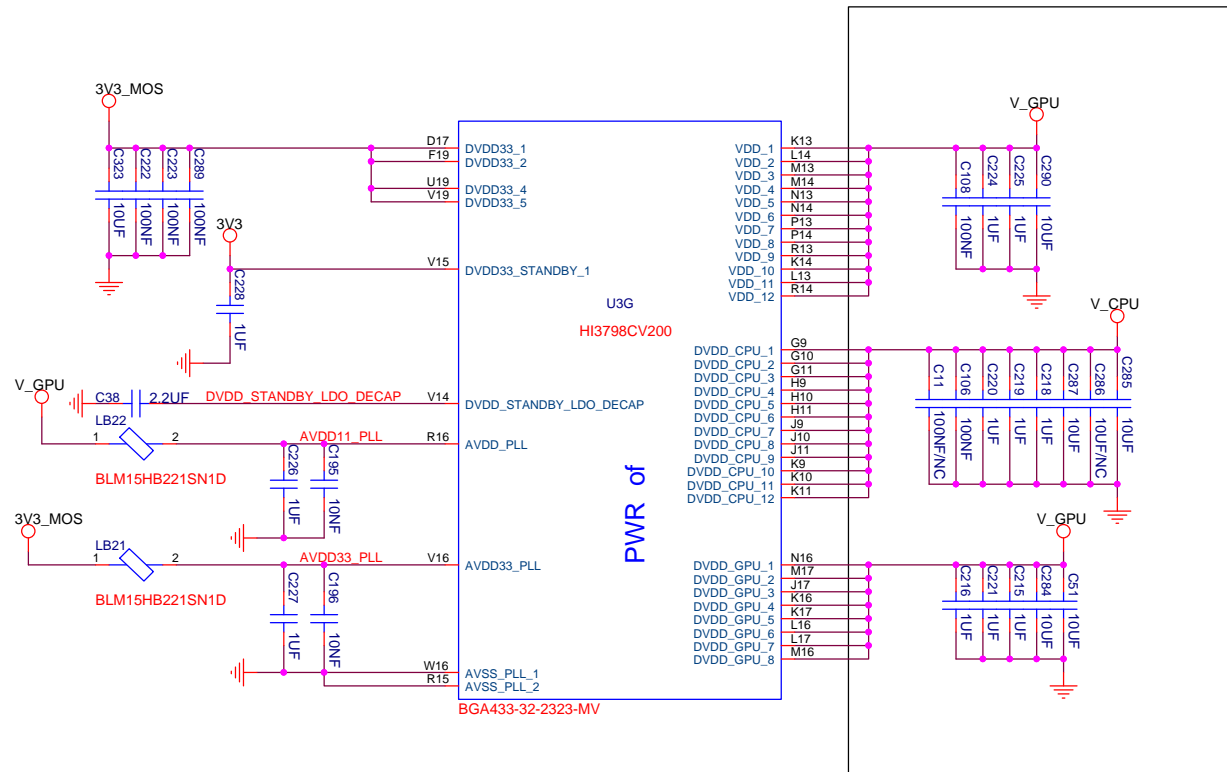
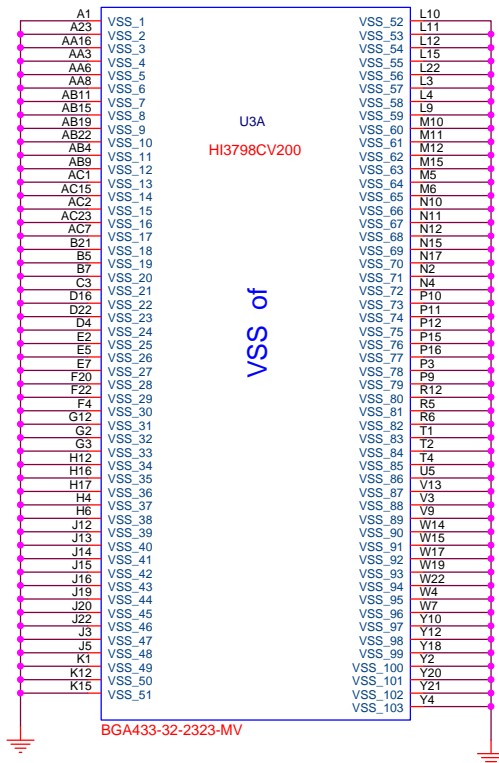
B.Layout suggestion

1. Please copy hisilicon demo board completely

The type and specification of the components refer to the BOM

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|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV20PB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 11 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

## Unit 6 of Hi3798CV200(POWER/VSS)

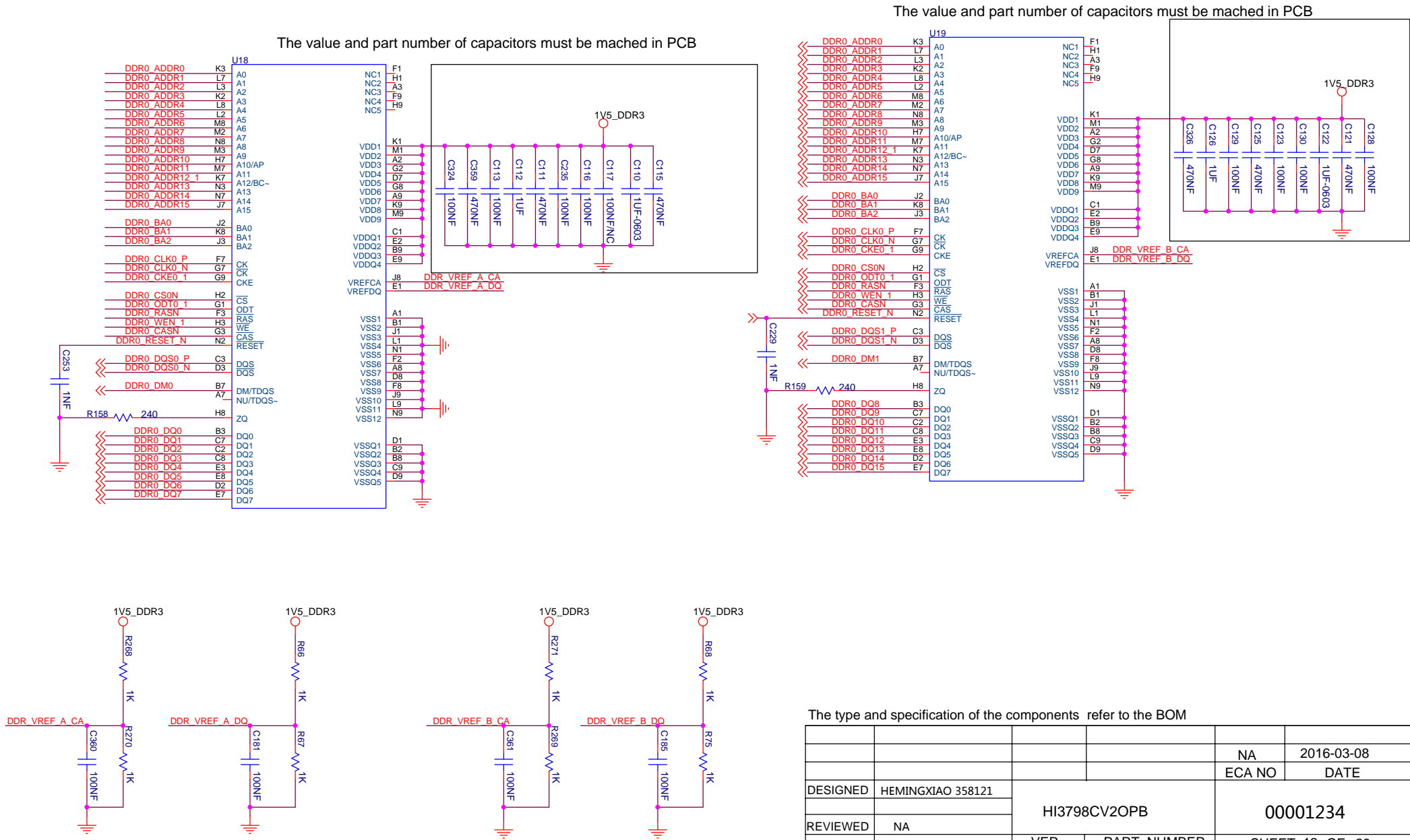


The value and part number of capacitors must be mached in PCB

The type and specification of the components refer to the BOM

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|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|          |                   |              |             |                      |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 12 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

DDR Byte0 & Byte1

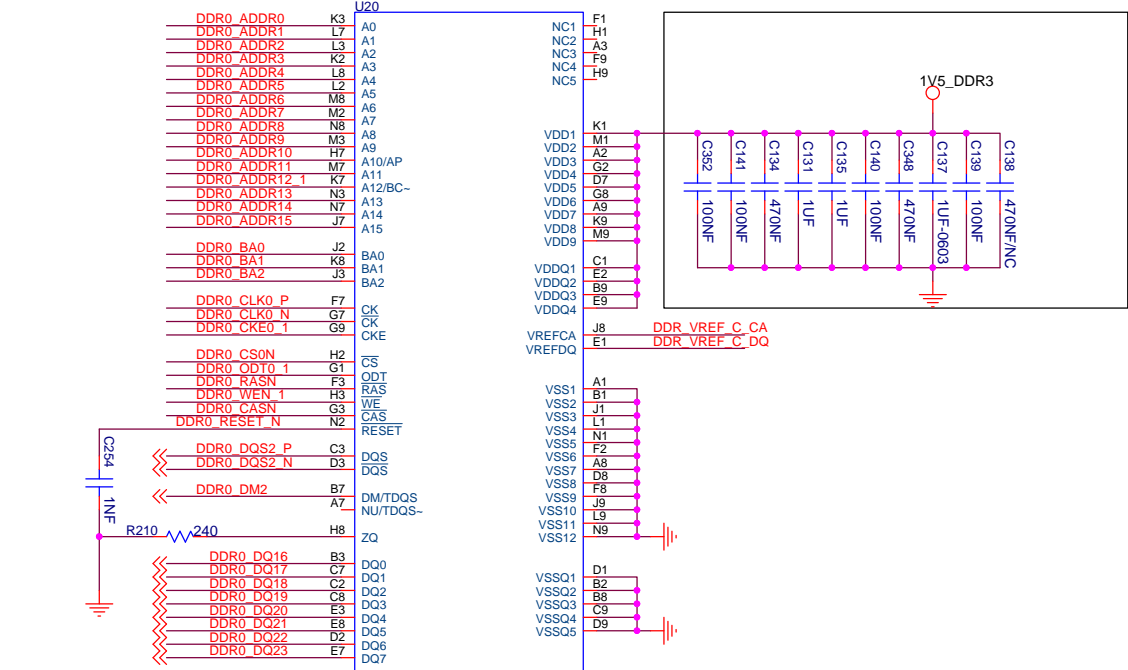


The type and specification of the components refer to the BOM

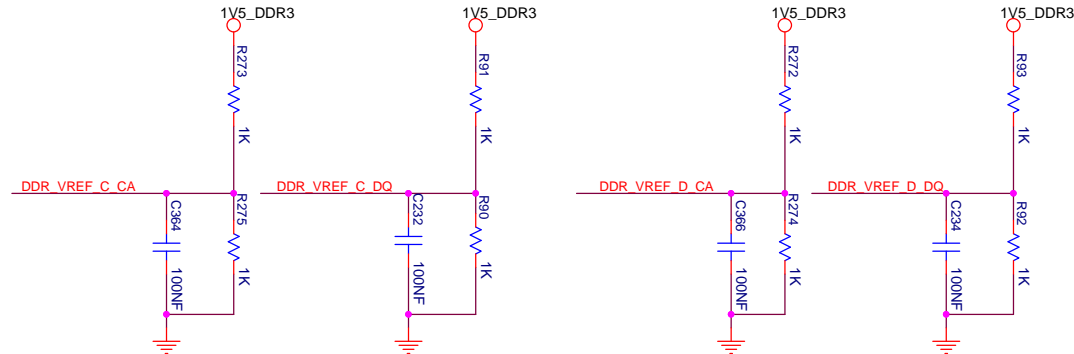
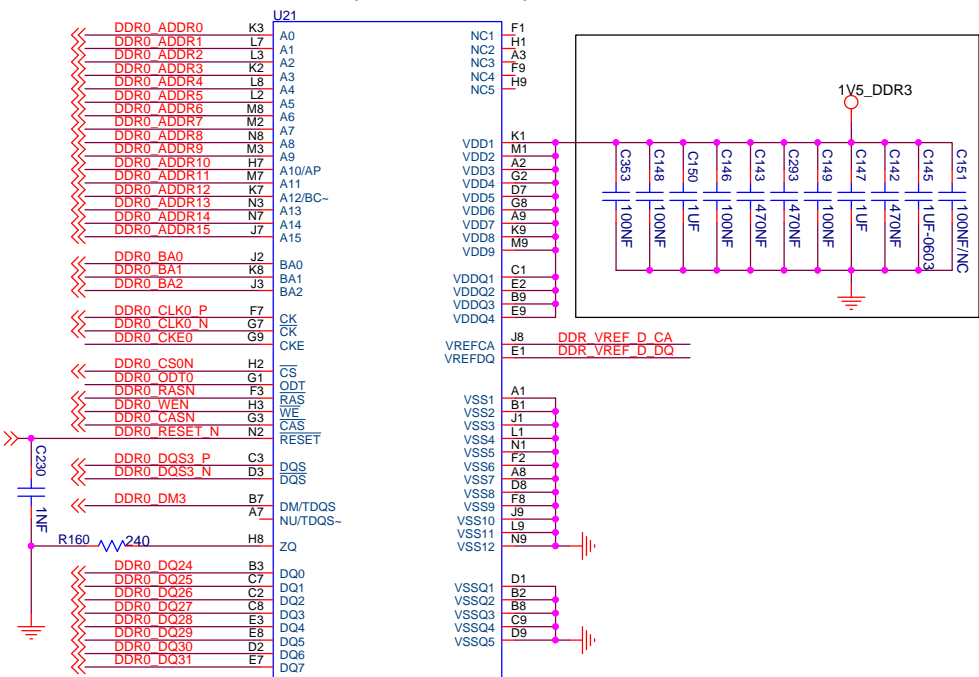
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| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                | VER          | PART_NUMBER | SHEET 13 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

DDR Byte2 & Byte3

The value and part number of capacitors must be mached in PCB



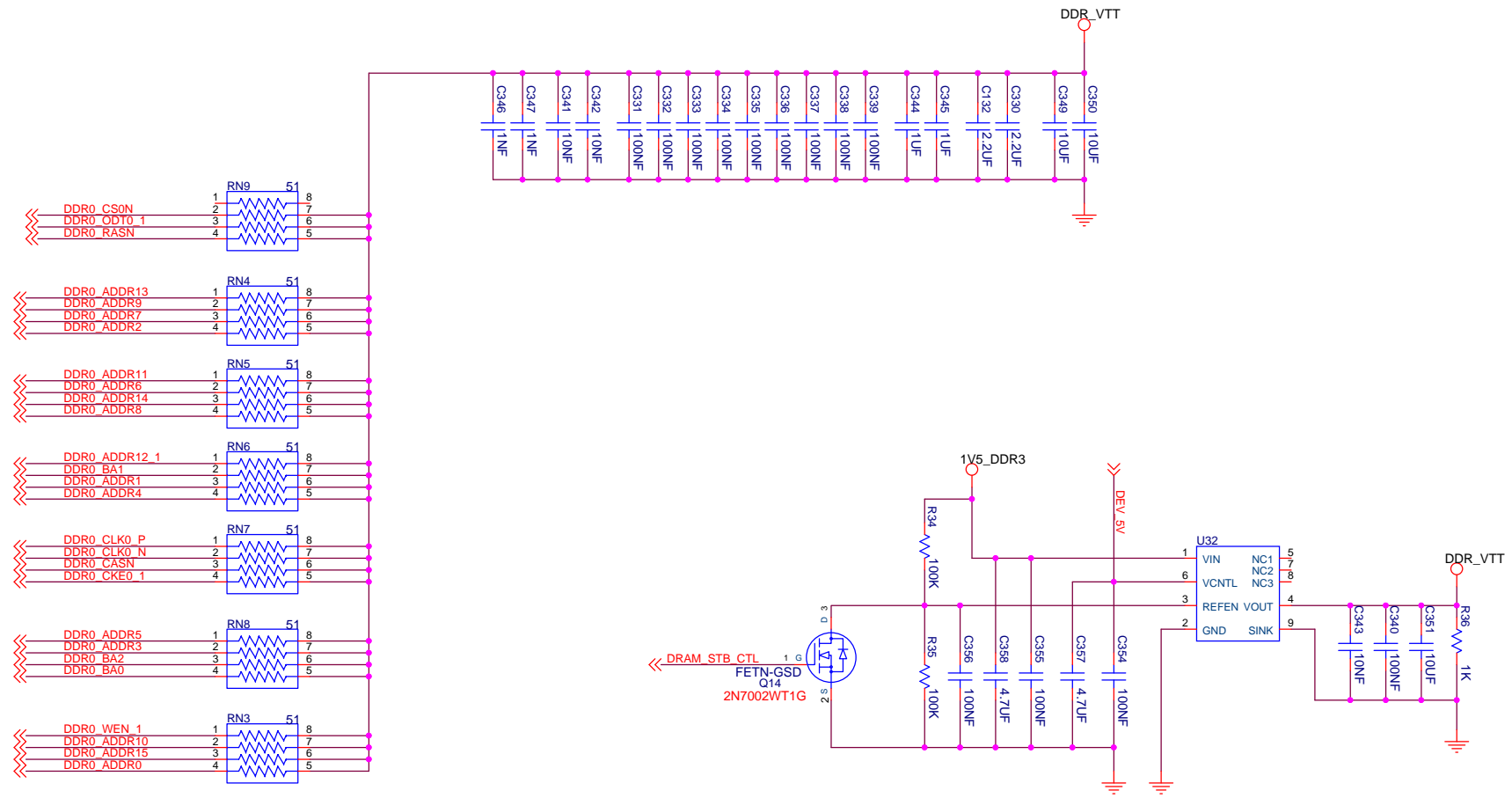
The value and part number of capacitors must be mached in PCB



The type and specification of the components refer to the BOM

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|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                | VER          | PART_NUMBER | SHEET 14 OF 28       |            |
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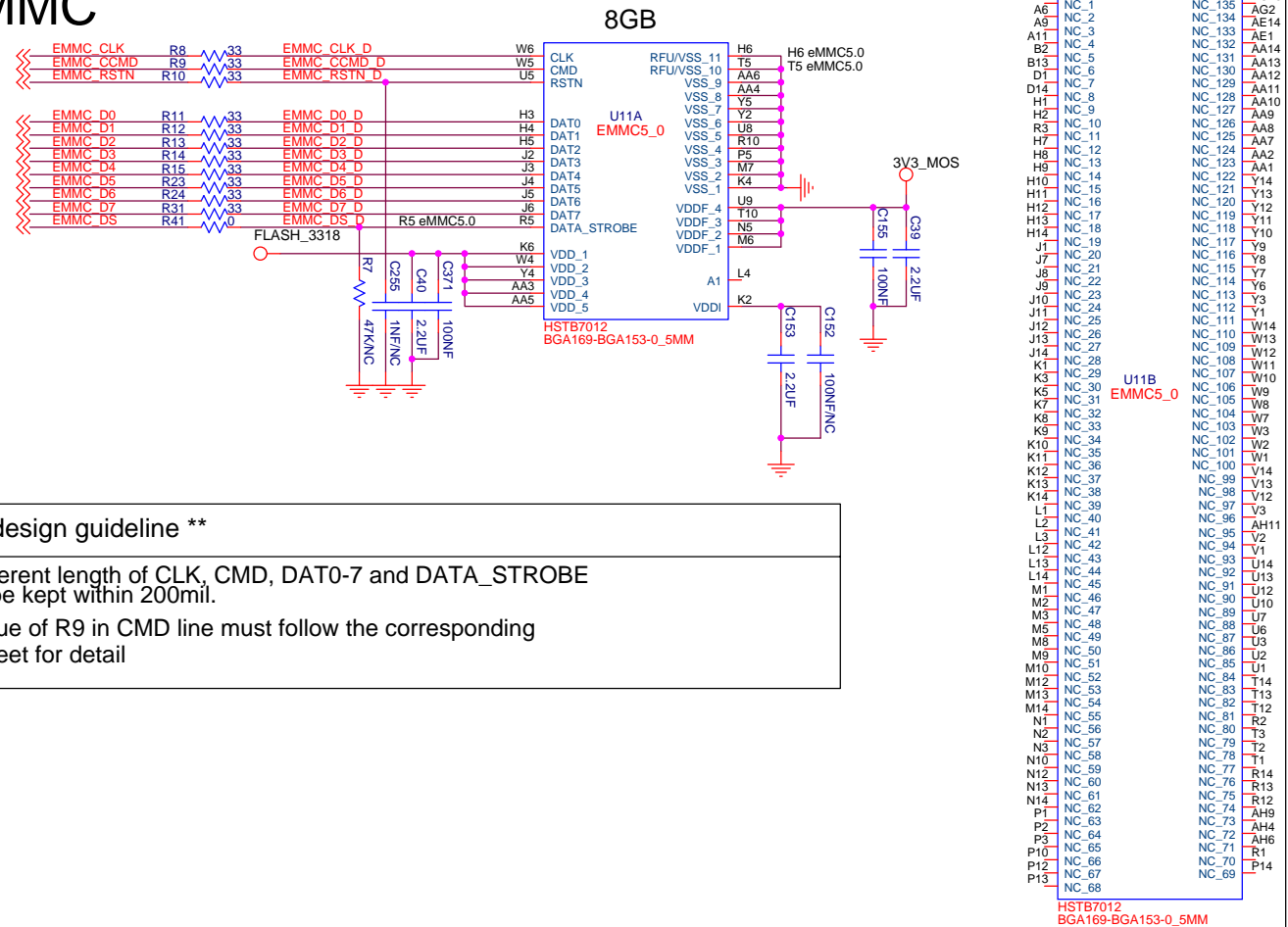
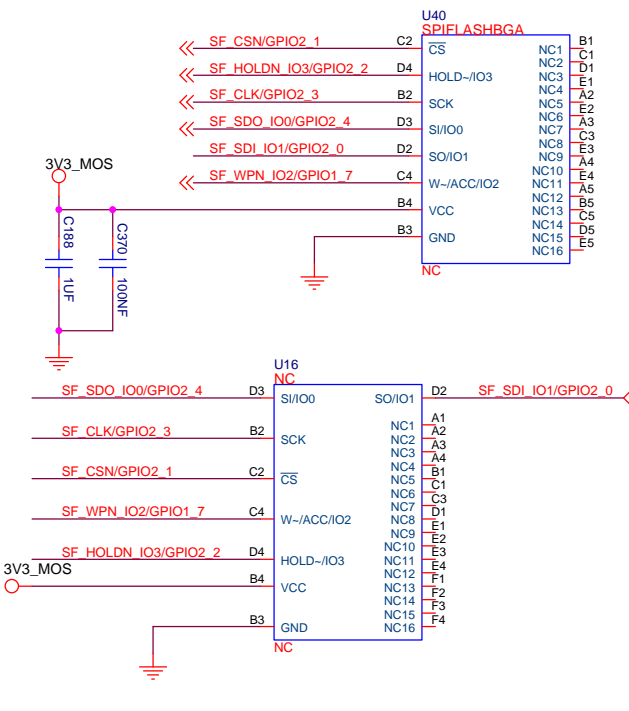
DDR VTT



The type and specification of the components refer to the BOM

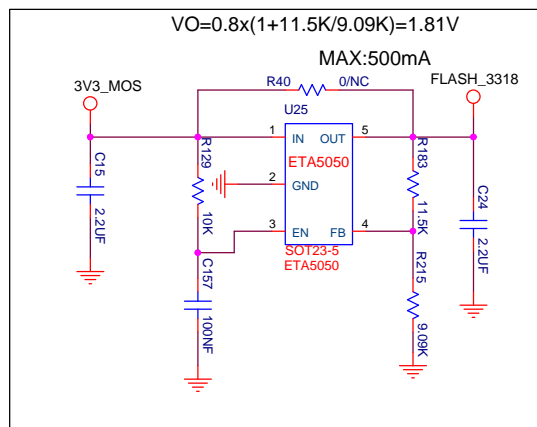
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| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 15 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

# NOR



**\*\* eMMC design guideline \*\***

1. The different length of CLK, CMD, DAT0-7 and DATA\_STROBE must be kept within 200mil.
2. The value of R9 in CMD line must follow the corresponding datasheet for detail



### 3.3V IO only For eMMC DDR50 Mode

R40 = 0 ohm  
others = NC

eMMC5.0(1.8V) default

### 1.8V IO For eMMC HS200\HS400 Mode

R40 = NC

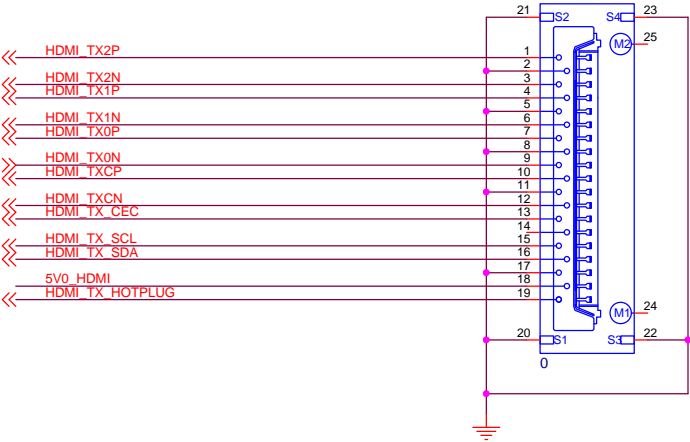
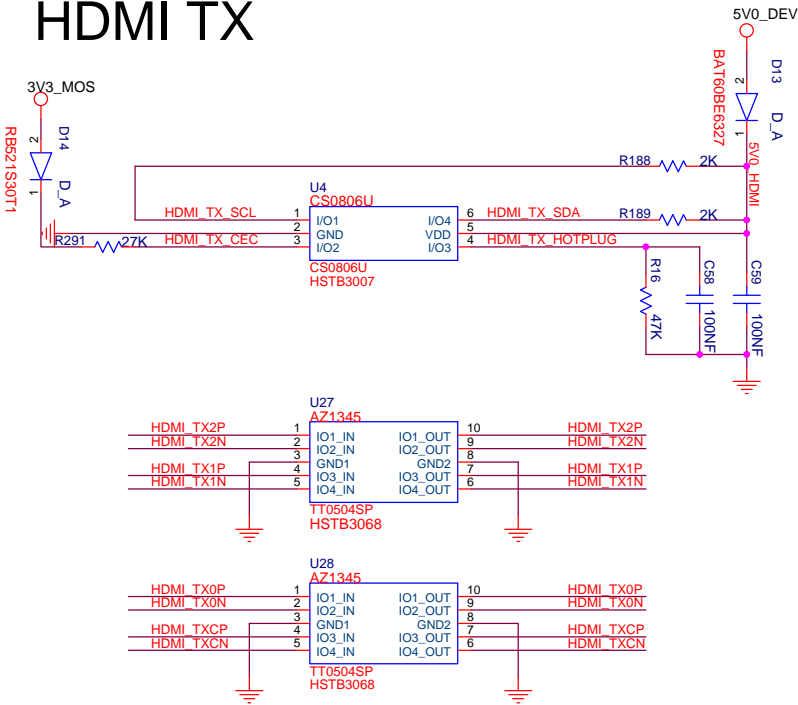
Others Mounted

The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
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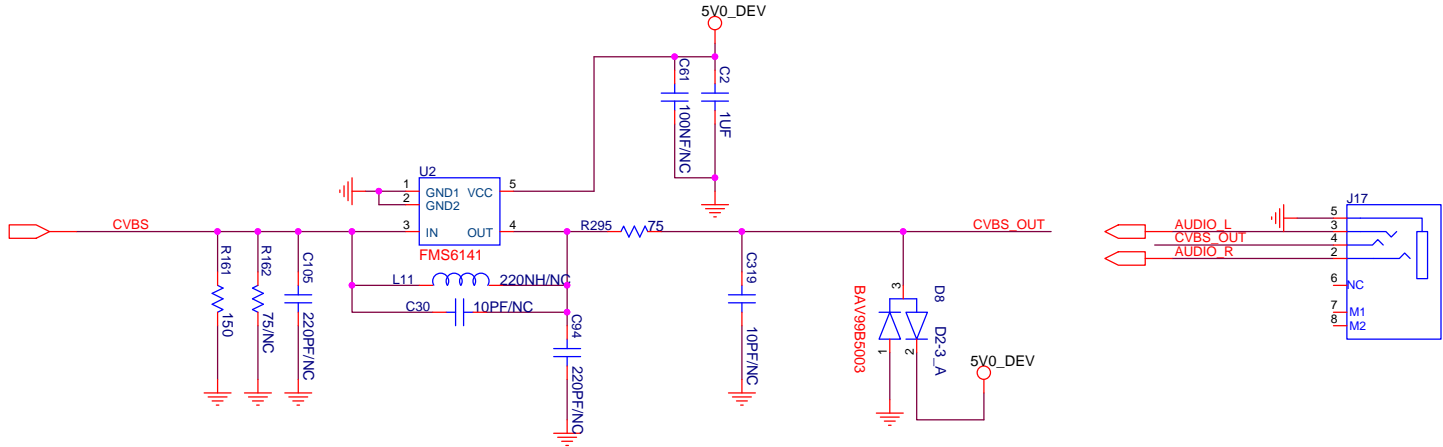


HDMI TX



VIDEO OUTPUT

| VIDEO BUFFER  | LC Filter     |
|---------------|---------------|
| R182 = 24K 1% | R182 = 12K 1% |
| R161 = 150 1% | R161 = 75 1%  |
| R162 = NC     | R162 = NC     |
| C105 = NC     | C105 = NC     |
| C30 = NC      | C30 = 10PF    |
| L11 = NC      | L11 = 220NH   |
| C94 = NC      | C94 = 220PF   |
| R295 = 75 1%  | R295 = 0      |
| C319 = NC     | C319 = NC     |
| C61 = NC      | C61 = NC      |
| C2 = 1UF      | C2 = NC       |
| U2 = FMS6141  | U2 = NC       |



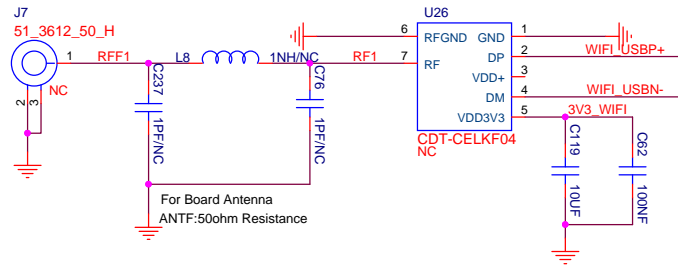
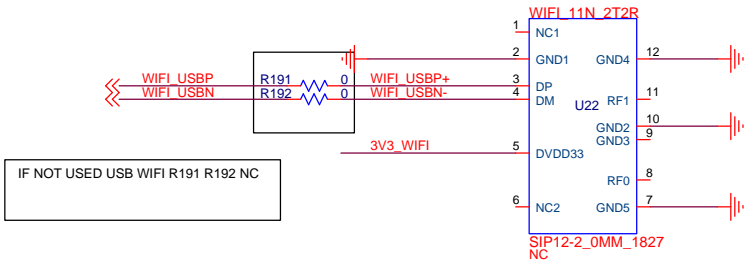
\*\* Design guideline \*\*

- 1.All channel traces should be separated from other traces by GND.
- 2.ESD components are suggested for ports protection, default BAV99.

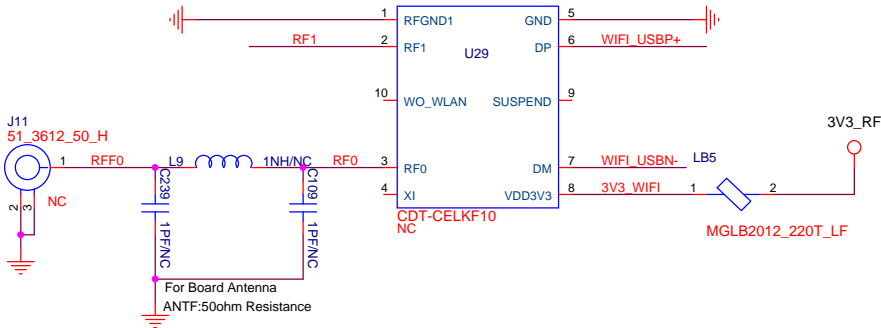
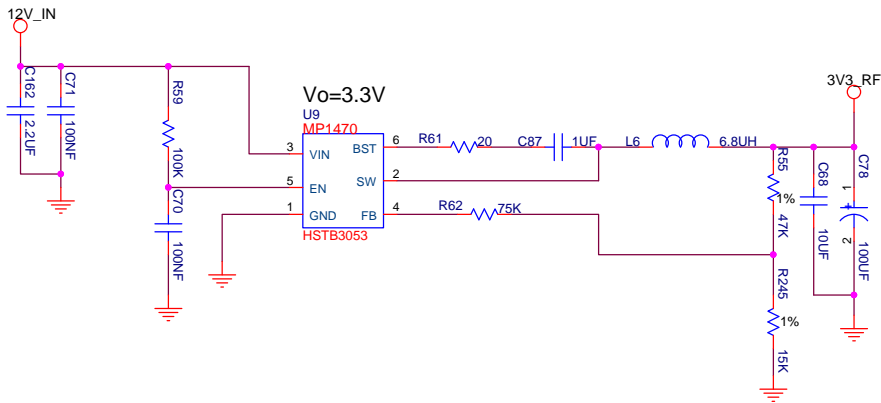
The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                | VER          | PART_NUMBER | SHEET 17 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

USB WIFI



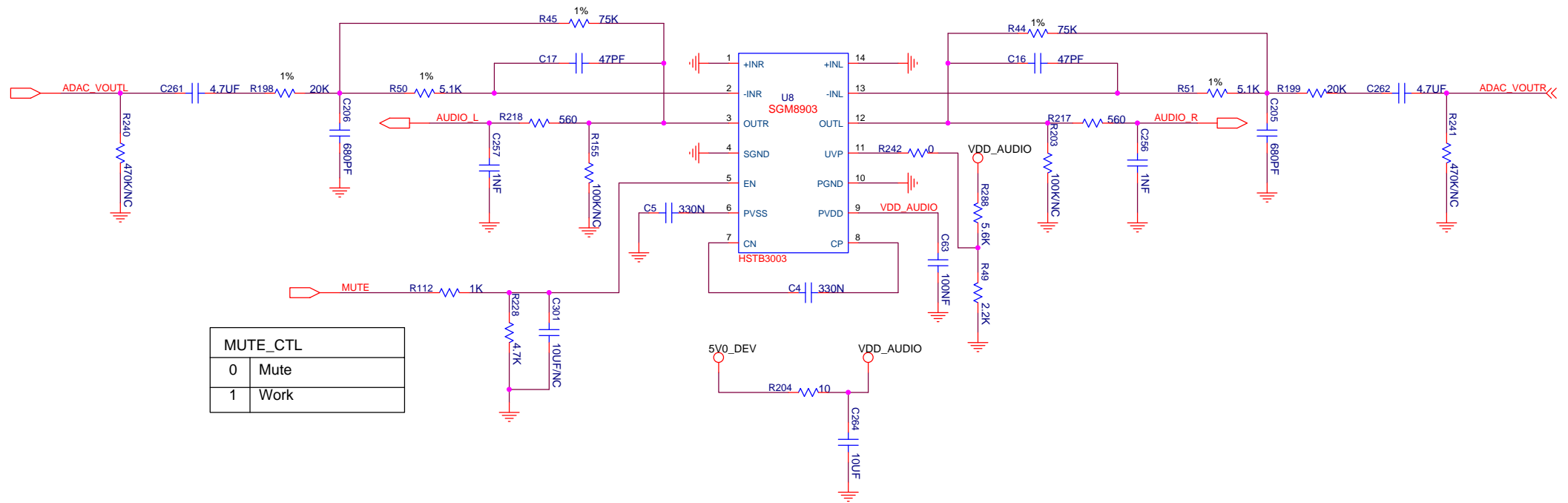
POWER OF WIFI



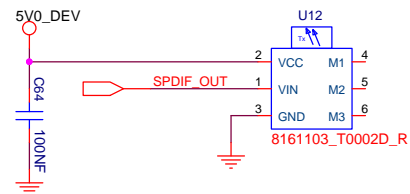
The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                | VER          | PART_NUMBER | SHEET 18 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

## AUDIO OUTPUT



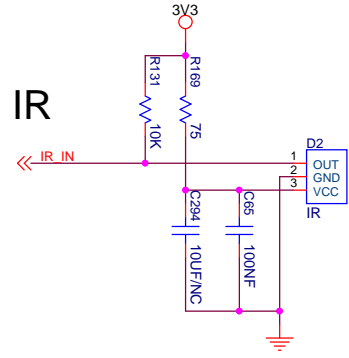
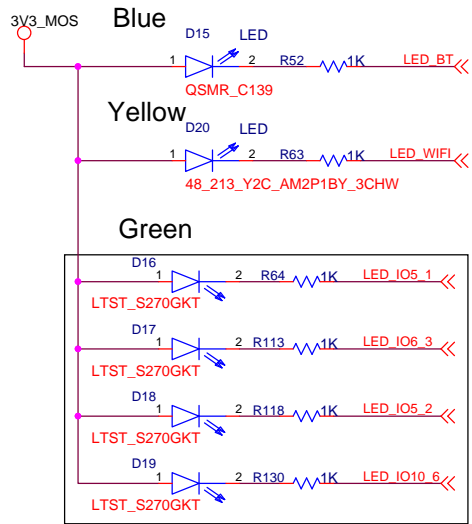
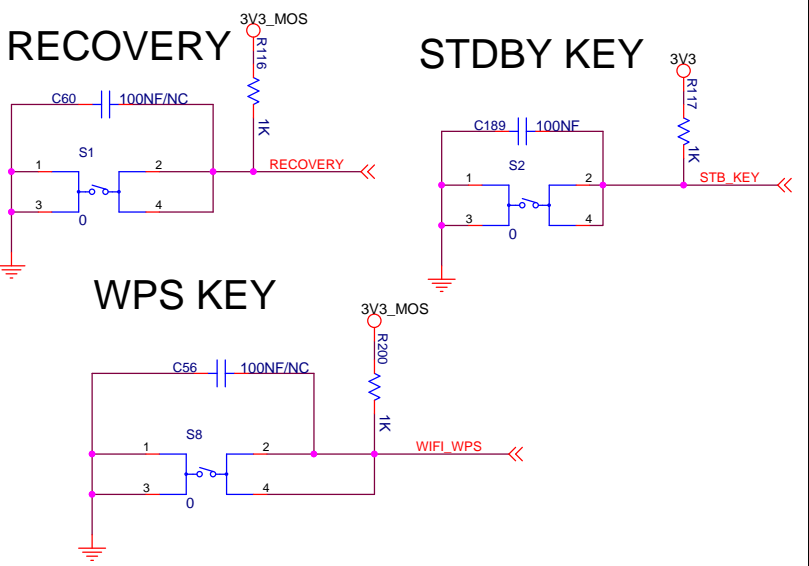
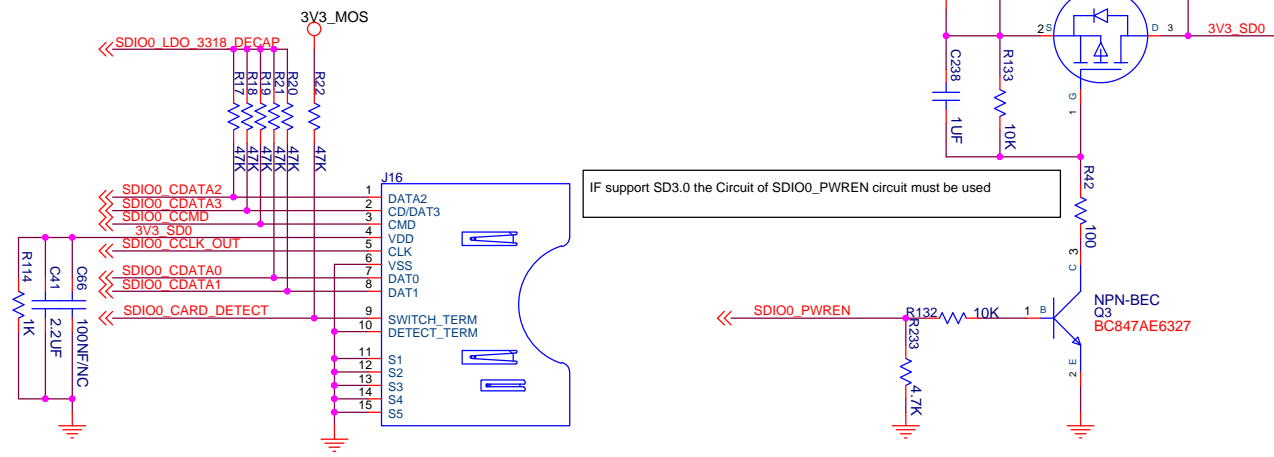
# SPDIF



The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|          |                   |              |             |                      |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 19 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

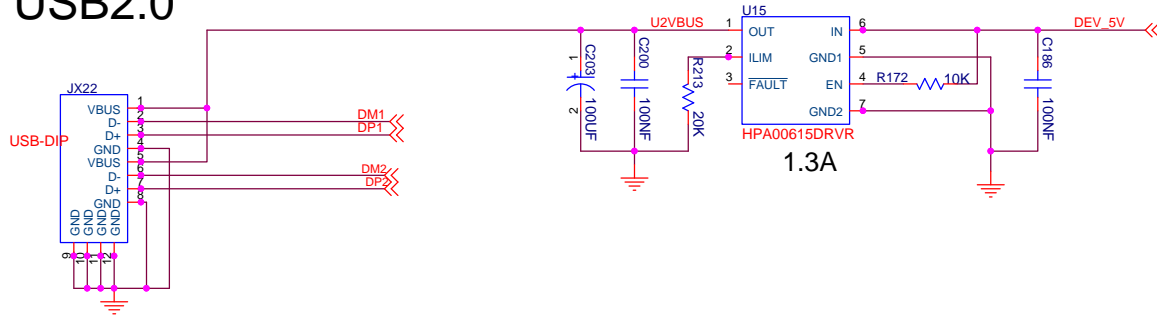
# SD CARD/IR/LED/KEY



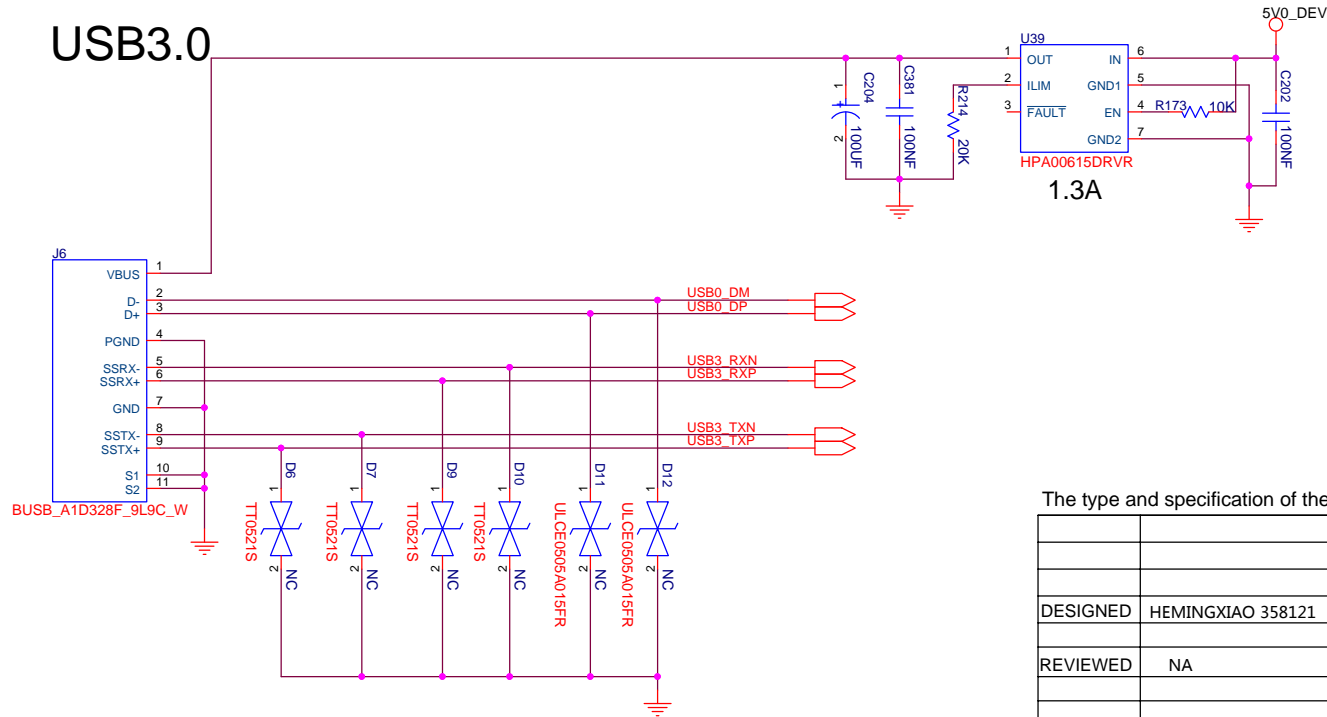
|   |                   |              |             |                      |            |
|---|-------------------|--------------|-------------|----------------------|------------|
| The type and specification of the components refer to the BOM |                   |              |             |                      |            |
|   |                   |              |             | NA                   | 2016-03-08 |
|   |                   |              |             | ECA NO               | DATE       |
| DESIGNED  | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED  | NA                |              |             |                      |            |
|   |                   | VER          | PART_NUMBER | SHEET 20 OF 28       |            |
|   |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

# USB2.0 & USB3.0

## USB2.0

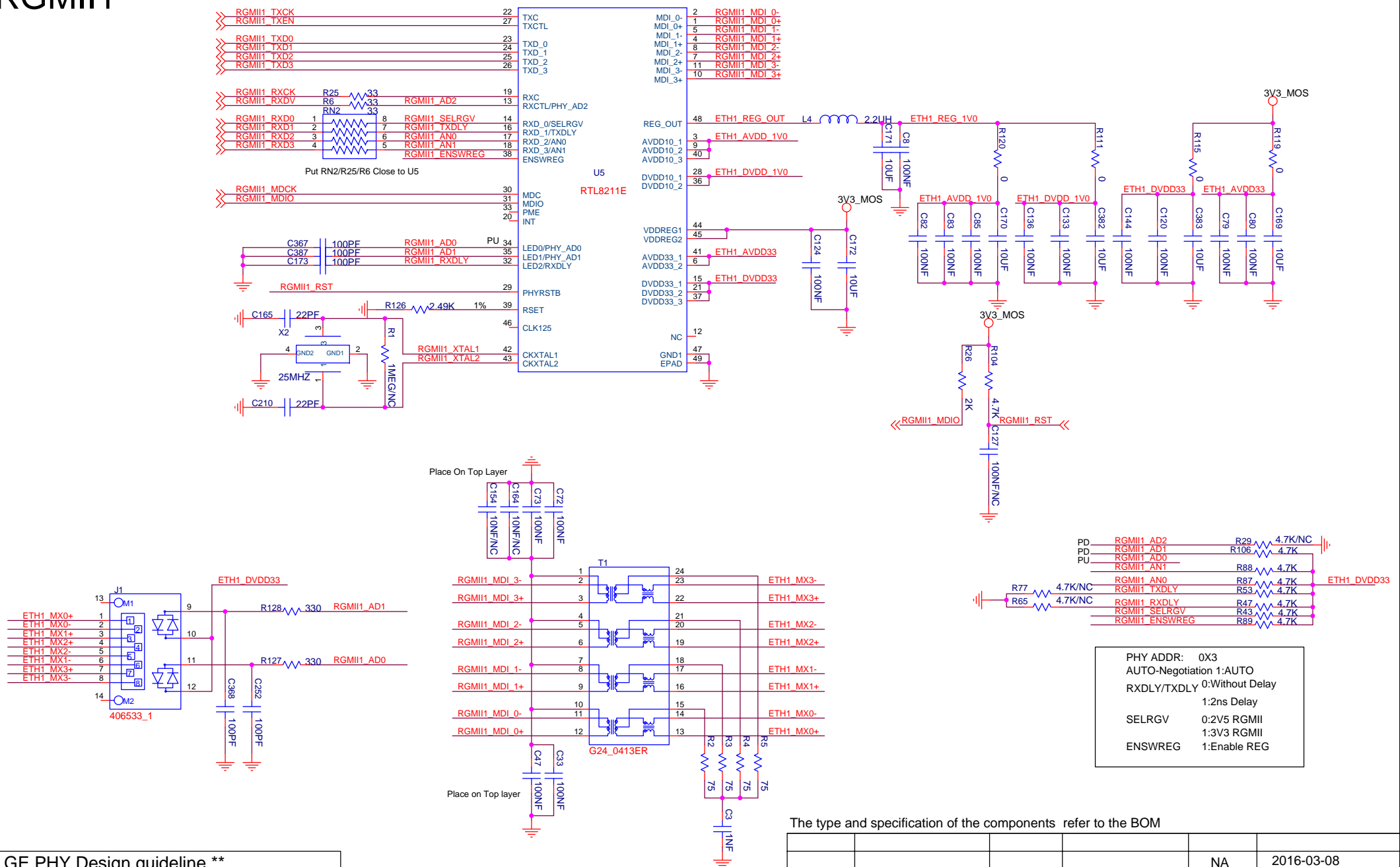


## USB3.0



The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                | VER          | PART_NUMBER | SHEET 21 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |



## \*\* GE PHY Design guideline \*\*

### A.RGMII interface

- 1.The TXCK and RXCK trace should be separated from other traces by GND.
- 2.The Power layout of GE PHY should copy Hisilicon demo completely.
- 3.The RXD[3:0] and TXD[3:0] should be separated from other traces by GND.

| The type and specification of the components refer to the BOM |                   |              |             |                      |            |
|---|-------------------|--------------|-------------|----------------------|------------|
|   |                   |              |             | NA                   | 2016-03-08 |
|   |                   |              |             | ECA NO               | DATE       |
| DESIGNED  | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|   |                   |              |             |                      |            |
| REVIEWED  | NA                |              |             |                      |            |
|   |                   | VER          | PART_NUMBER | SHEET 22 OF 28       |            |
|   |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

The schematic diagram illustrates the electrical connections for the J14 connector on the SDW12501A\_8A\_HW board. The connector is an 8-pin header with pins labeled A8 through A1. The connections are as follows:

- Pin 8 (A8):** Connected to the 3V3\_MOS supply through a 100nF capacitor (C54) to ground.
- Pin 7 (A7):** Connected to the 3V3\_MOS supply through a 4.7kΩ resistor (R225).
- Pin 6 (A6):** Connected to the 3V3\_MOS supply through a 4.7kΩ resistor (R224).
- Pin 5 (A5):** Connected to the 3V3\_MOS supply through a 1kΩ resistor (R108).
- Pin 4 (A4):** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R122).
- Pin 3 (A3):** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R100).
- Pin 2 (A2):** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R101).
- Pin 1 (A1):** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R102).

The JTAG pins are connected to the 3V3\_MOS supply through resistors:

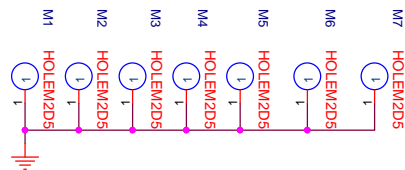
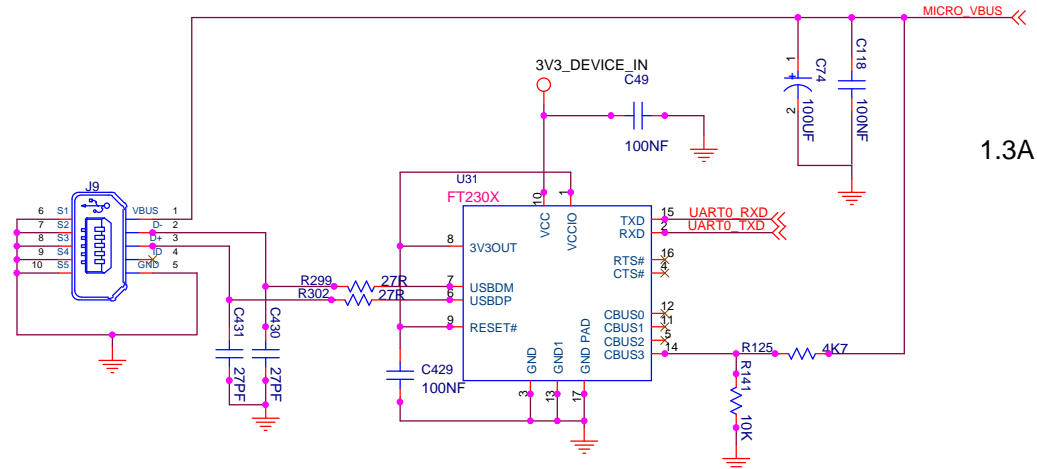
- JTAG TDO:** Connected to the 3V3\_MOS supply through a 4.7kΩ resistor (R225).
- JTAG TCK:** Connected to the 3V3\_MOS supply through a 4.7kΩ resistor (R224).
- JTAG TMS:** Connected to the 3V3\_MOS supply through a 1kΩ resistor (R108).
- JTAG TDI:** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R100).
- JTAG TRSTN:** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R101).

The I2C pins are connected to the 3V3\_MOS supply through resistors:

- I2C2 SCL:** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R100).
- I2C2 SDA:** Connected to the 3V3\_MOS supply through a 10kΩ resistor (R101).

The DEMO\_RST pin is connected to the 3V3\_MOS supply through a 10kΩ resistor (R102).

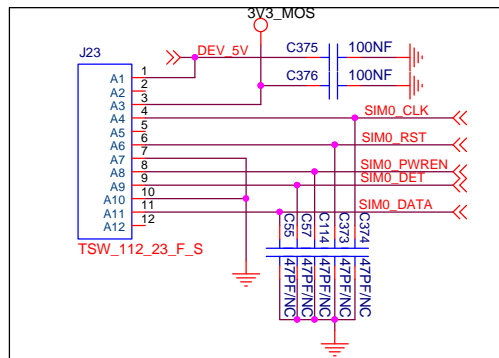
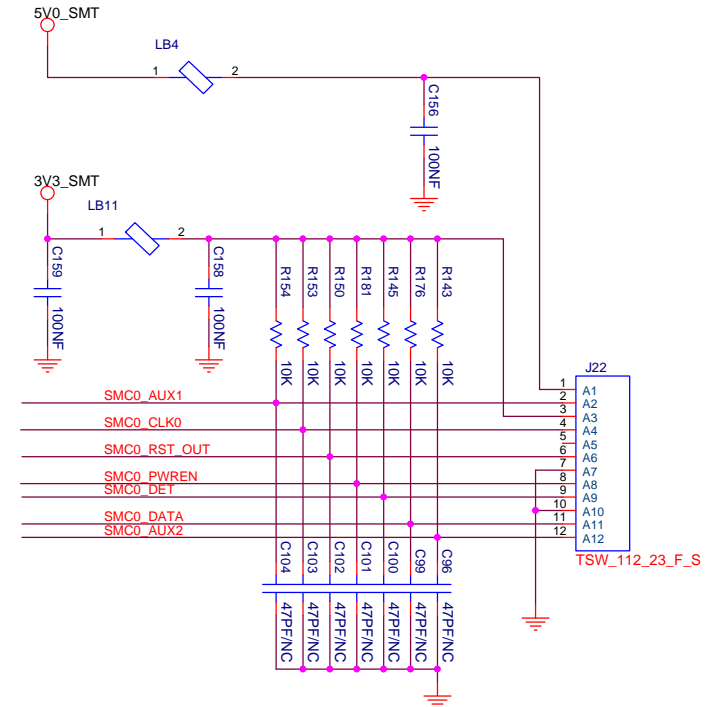
SDW12501\_4A\_HW



The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|          |                   |              |             |                      |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 23 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

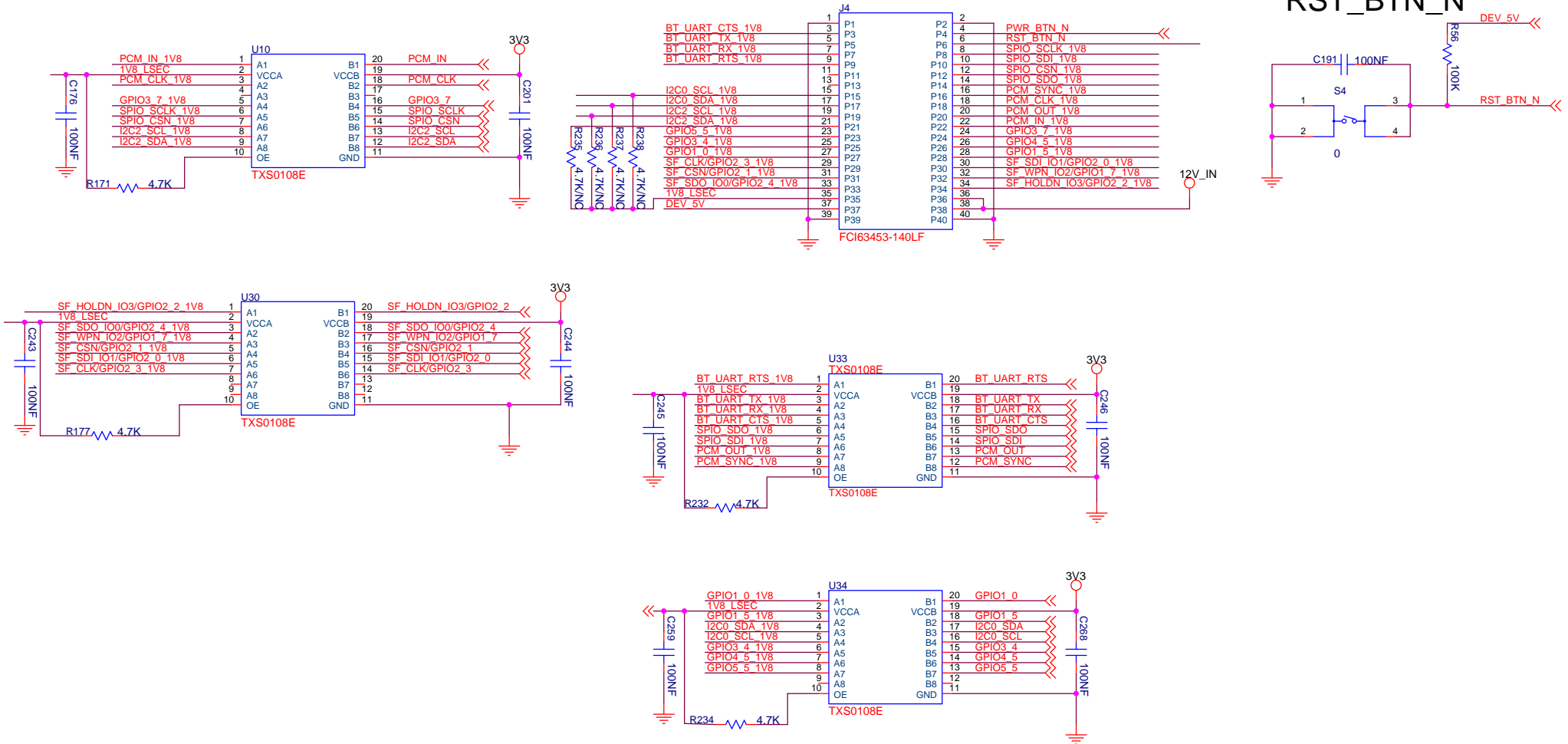
# Connector for Smart Card Board



|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|          |                   |              |             |                      |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 24 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |
|          |                   |              |             |                      |            |



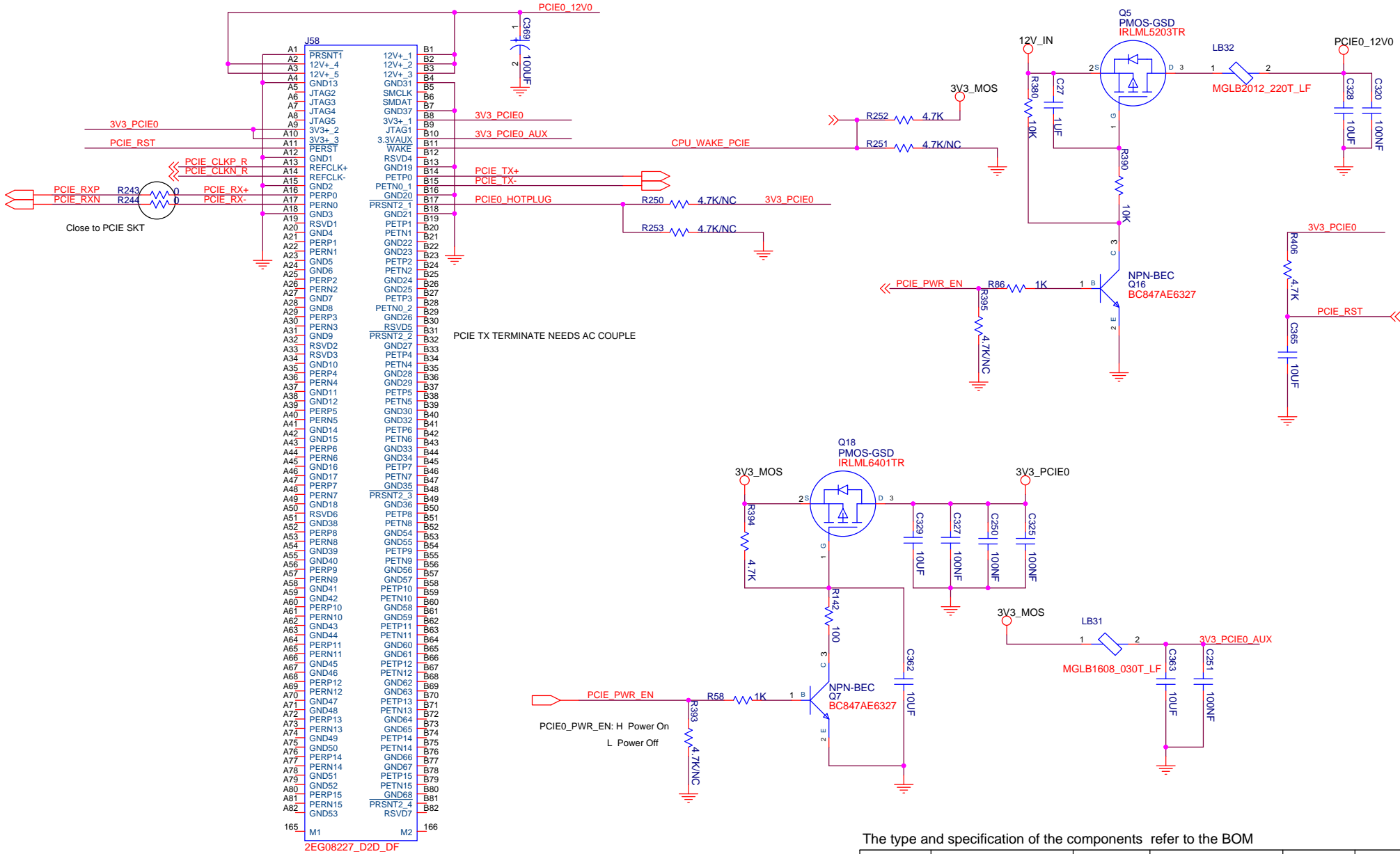
Low Speed Expansion Connector(LSEC)



The type and specification of the components refer to the BOM

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 25 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

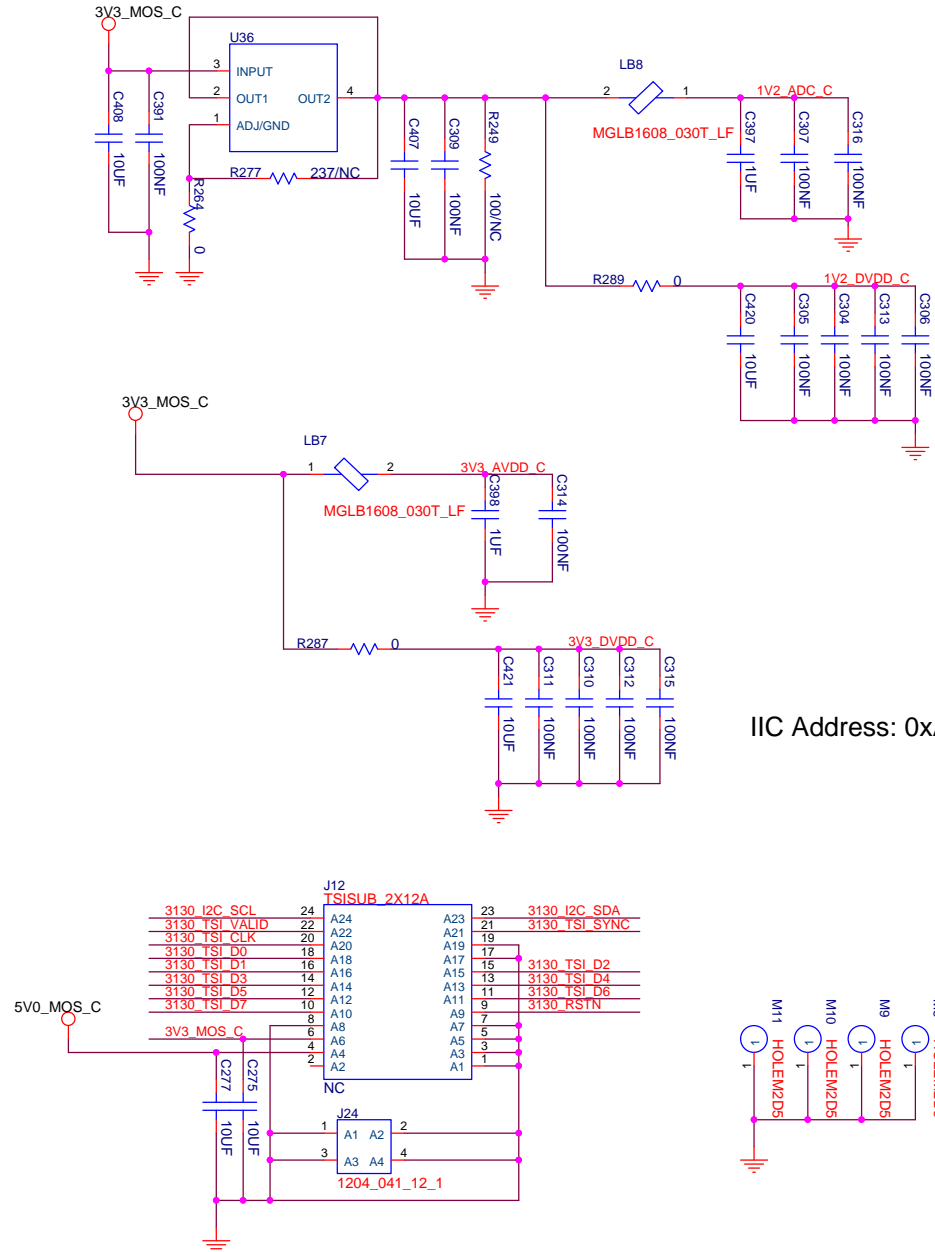
PCIe 1 lane



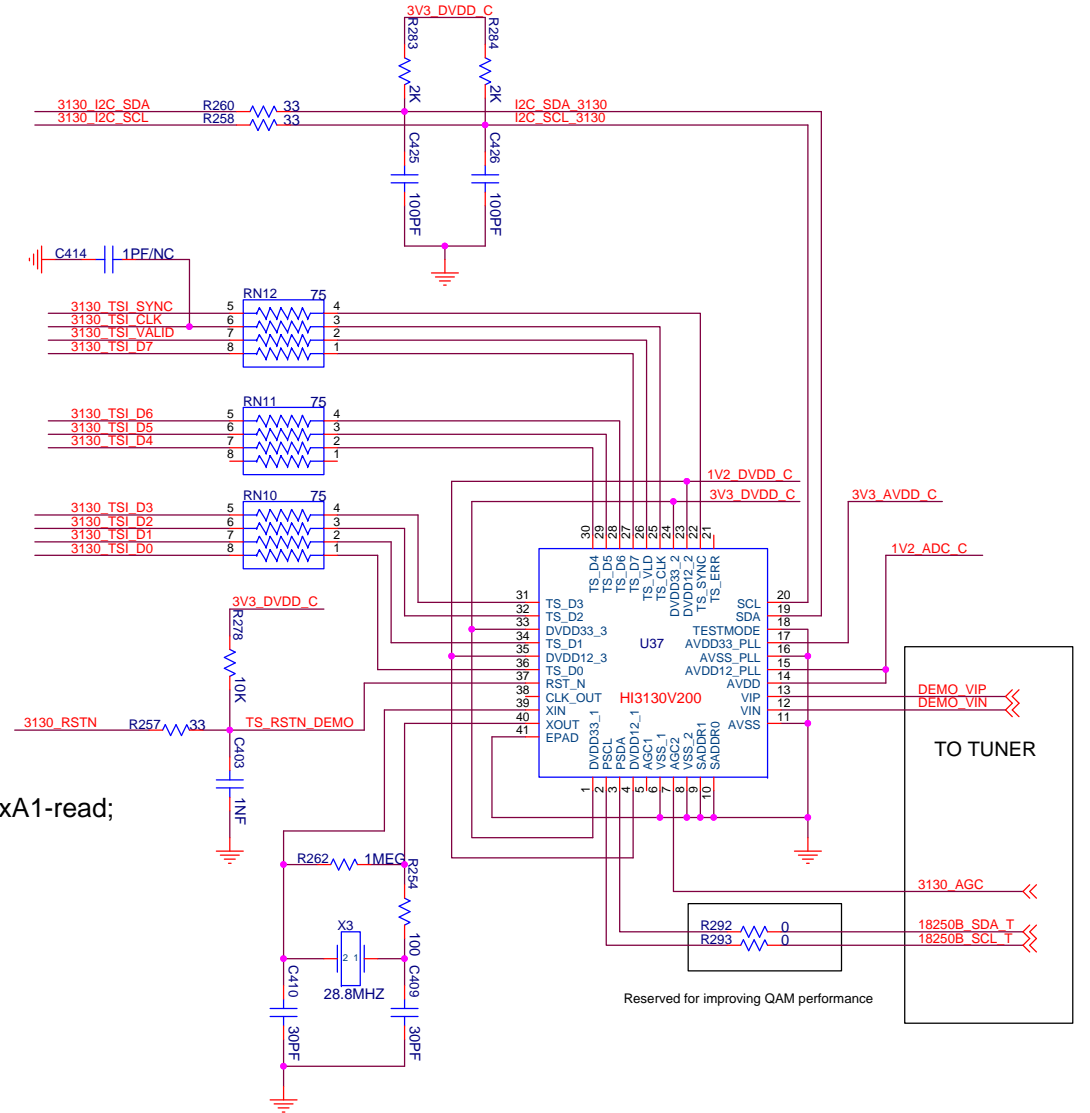
PCIe\_Socket

|   |                   |              |             |                      |            |
|---|-------------------|--------------|-------------|----------------------|------------|
| The type and specification of the components refer to the BOM |                   |              |             |                      |            |
|   |                   |              |             | NA                   | 2016-03-08 |
|   |                   |              |             | ECA NO               | DATE       |
| DESIGNED  | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
| REVIEWED  | NA                |              |             |                      |            |
|   |                   | VER          | PART_NUMBER | SHEET 26 OF 28       |            |
|   |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |

# HI3130V200

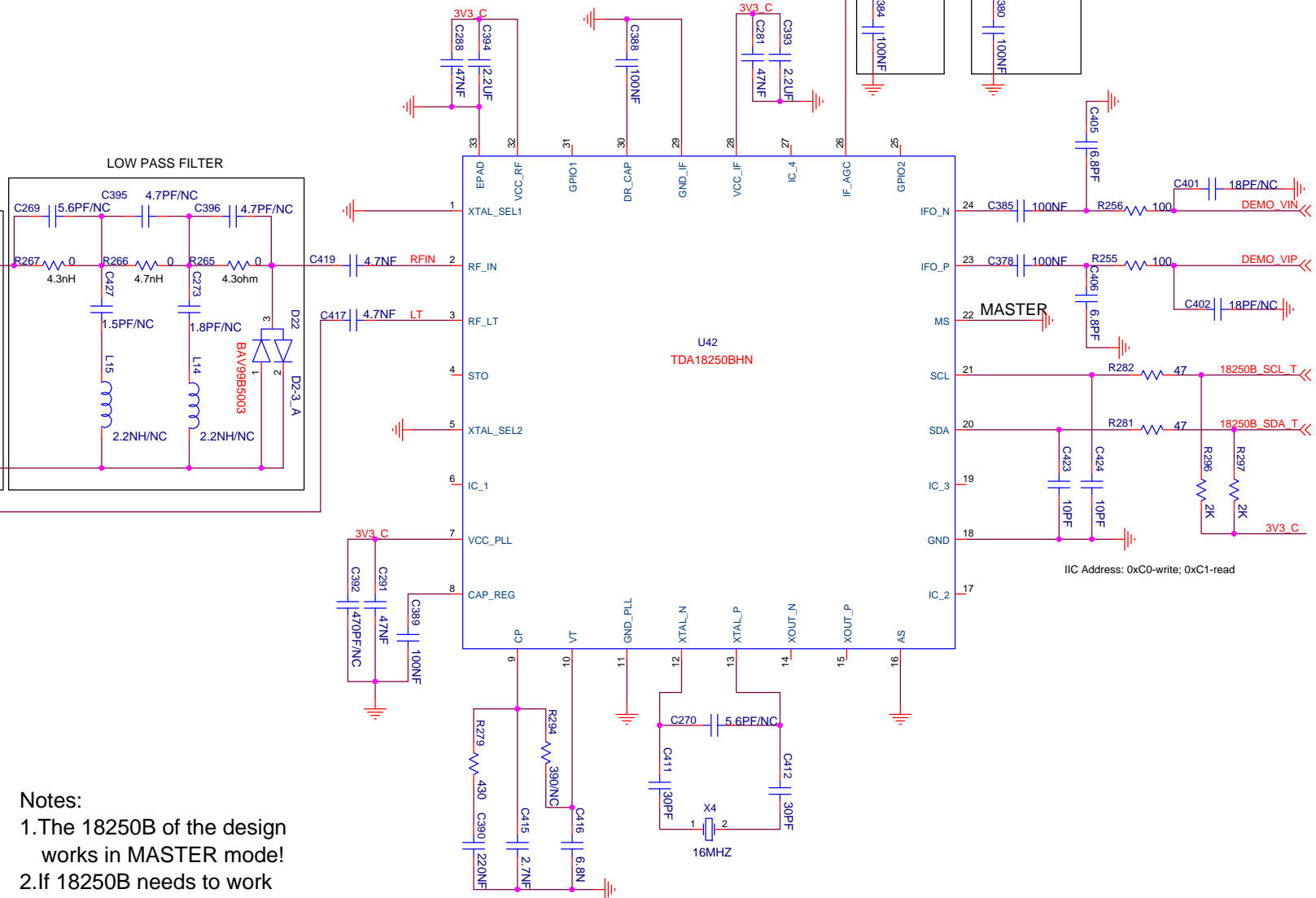


IIC Address: 0xA0-write; 0xA1-read;



The type and specification of the components refer to the BOM

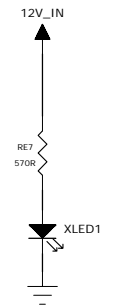
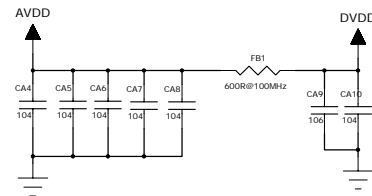
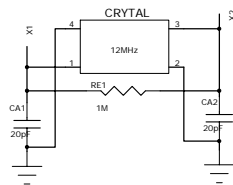
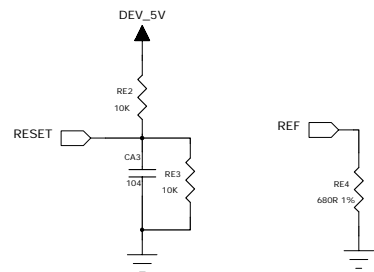
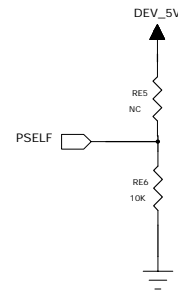
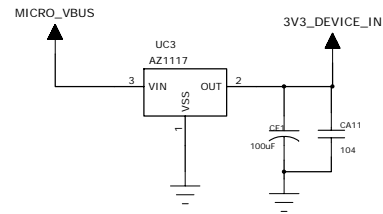
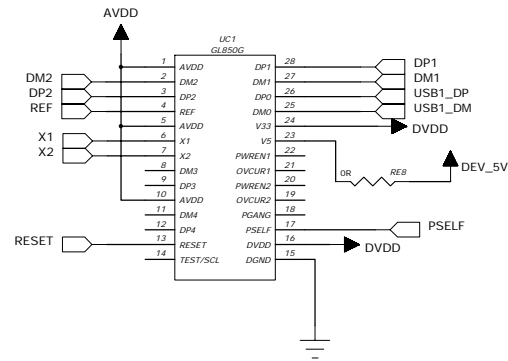
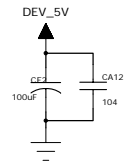
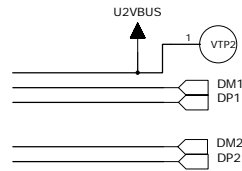
|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|          |                   |              |             |                      |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 27 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |



1. The 18250B of the design works in MASTER mode!
2. If 18250B needs to work in SLAVE mode, please see below:
  - 1) Connect PIN22 MS to 3.3V.
  - 2) Connect PIN2 RF\_IN via capacitor to PIN4 STO of an upper-stage 18250B
  - 3) Connect PIN12&PIN13 via capacitors to PIN14&PIN15 of the upper-stage 18250B, respectively.

|          |                   |              |             |                      |            |
|----------|-------------------|--------------|-------------|----------------------|------------|
|          |                   |              |             |                      |            |
|          |                   |              |             | NA                   | 2016-03-08 |
|          |                   |              |             | ECA NO               | DATE       |
| DESIGNED | HEMINGXIAO 358121 | HI3798CV2OPB |             | 00001234             |            |
|          |                   |              |             |                      |            |
| REVIEWED | NA                |              |             |                      |            |
|          |                   | VER          | PART_NUMBER | SHEET 28 OF 28       |            |
|          |                   | A            | 03030001    | HUAWEI TECH CO.,LTD. |            |
|          |                   |              |             |                      |            |

# HUB



Power indicator light